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CY8CLED16 EZ-Color™ HB LED Controller

Features

- HB LED Controller
 - Configurable dimmers support up to 16 Independent LED channels
 - 8-to 32-bits of resolution per channel
 - Dynamic reconfiguration Enables LED controller Plus Other Features: CapSense[®], battery charging, and motor control
- Visual embedded design

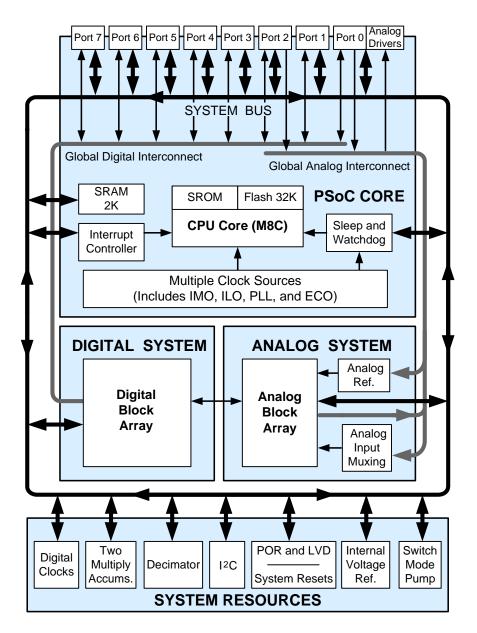
LED-based drivers

- Binning compensation
- Temperature feedback
- Optical feedback
- DMX512
- PrISM modulation technology[™]
 - Reduces radiated EMI
 - Reduces low frequency blinking
- Powerful Harvard-architecture Processor
 - M8C processor speeds to 24 MHz
 - 3.0 to 5.25 V operating voltage
 - Operating voltages down to 1.0 V using On-Chip switch mode pump (SMP)
 Industrial temperature range: -40 °C to +85 °C
- Programmable pin configurations
 - □ 25 mA sink, 10 mA source on all GPIO
 - Pull-up, Pull-down, High Z, Strong, or Open Drain Drive Modes on all GPIO
 - Up to eight analog Inputs on GPIO
 - Configurable interrupt on all GPIO

- Advanced peripherals (PSoC[®] Blocks)
 - I6 Digital PSoC Blocks Provide:
 - 8-to 32-bit timers, counters, and PWMs
 - Up to 4 Full-Duplex UARTs
 - Multiple SPI masters or slaves
 - Connectable to all GPIO Pins
 - □ 12 Rail-to-Rail Analog PSoC Blocks Provide:
 - Up to 14-Bit ADCs
 - Up to 9-Bit DACs
 - · Programmable gain amplifiers
 - Programmable filters and comparators
 - Complex peripherals by combining blocks
- Flexible on-chip memory
 - □ 32K flash program storage 50,000 Erase/Write Cycles
 - 2K SRAM Data Storage
 - In-system serial programming (ISSP)
 - Partial flash updates
 - Flexible Protection Modes
 - electrically erasable programmable read-only memory (EEPROM) emulation in flash
- Complete development tools
 - □ Free development software
 - PSoC Designer™
 - □ Full-featured, In-circuit emulator and programmer
 - □ Full speed emulation
 - Complex breakpoint structure
 - 128 KB trace memory



Logic Block Diagram





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EZ-Color™ Functional Overview

Cypress's EZ-Color family of devices offers the ideal control solution for High Brightness LED applications requiring intelligent dimming control. EZ-Color devices combine the power and flexibility of Programmable System-on-Chip (PSoC); with Cypress's precise illumination signal modulation (PrISM) modulation technology providing lighting designers a fully customizable and integrated lighting solution platform.

The EZ-Color family supports a range of independent LED channels from 4 channels at 32 bits of resolution each, up to 16 channels at 8 bits of resolution each. This enables lighting designers the flexibility to choose the LED array size and color quality. PSoC Designer software, with lighting specific drivers, can significantly cut development time and simplify implementation of fixed color points through temperature, optical, and LED binning compensation. EZ-Color's virtually limitless analog and digital customization allow for simple integration of features in addition to intelligent lighting, such as Battery Charging, Image Stabilization, and Motor Control during the development process. These features, along with Cypress' best-in-class quality and design support, make EZ-Color the ideal choice for intelligent HB LED control applications.

Target Applications

- LCD Backlight
- Large Signs
- General Lighting
- Architectural Lighting
- Camera/Cell Phone flash
- flashlights

The PSoC Core

The PSoC core is a powerful engine that supports a rich feature set. The core includes a central processing unit (CPU), memory, clocks, and configurable general purpose I/O (GPIO).

The M8C CPU core is a powerful processor with speeds up to 48 MHz, providing a four million instructions per second (MIPS) 8-bit Harvard-architecture microprocessor. The CPU utilizes an interrupt controller with 25 vectors, to simplify programming of real time embedded events. Program execution is timed and protected using the included Sleep and watchdog timers (WDT).

Memory encompasses 32 KB of flash for program storage, 2 KB of SRAM for data storage, and up to 2 KB of EEPROM emulated using the flash. Program flash utilizes four protection levels on blocks of 64 bytes, allowing customized software IP protection.

The EZ-Color family incorporates flexible internal clock generators, including a 24 MHz internal main oscillator (IMO) accurate to 2.5% over temperature and voltage. The 24 MHz IMO can also be doubled to 48 MHz for use by the digital system. A low power 32 kHz internal low speed oscillator (ILO) is provided for the Sleep timer and WDT. If crystal accuracy is desired, the 32.768 kHz external crystal oscillator (ECO) is available for use as a real time clock (RTC) and can optionally generate a crystal-accurate 24 MHz system clock using a PLL. The clocks, together with programmable clock dividers (as a System Resource), provide the flexibility to integrate almost any timing requirement into the EZ-Color device.

EZ-Color GPIOs provide connection to the CPU, digital and analog resources of the device. Each pin's drive mode may be selected from eight options, allowing great flexibility in external interfacing. Every pin also has the capability to generate a system interrupt on high level, low level, and change from last read.

The Digital System

The digital system is composed of 16 digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include those listed below.

- PrISM (8-to 32-bit)
- PWMs (8-to 32-bit)
- PWMs with Dead band (8-to 32-bit)
- Counters (8-to 32-bit)
- Timers (8-to 32-bit)
- UART 8 bit with selectable parity (up to 4)
- SPI master and slave (up to 4 each)
- I²C slave and multi-master (1 available as a System Resource)
- Cyclical Redundancy Checker/Generator (8- to 32-bit)
- IrDA (up to 4)
- Generators (8-to 32-bit)

The digital blocks can be connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by EZ-Color device family. This allows you the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 6.



Port 7 Port 5 Port 3 Port 1 Port 0 Port 6 Port 4 Port 2 To System Bus **Digital Clocks** To Analog From Core System DIGITAL SYSTEM **Digital PSoC Block Array** Row 0 Configuration Row Output DBB00 DBB01 DCB02 DCB03 Configu ¥. 8 Row 1 Configuration Row Configuratio ¥ DBB10 DBB11 v Output DCB12 DCB13 Row 2 Configuration Row ¥ DBB20 DBB21 DCB22 DCB23 / Output Row 3 Configuration Configuration Row put DBB30 DBB31 DCB32 DCB33 Output ¥ 4 GIE[7:0] GOE[7:0] Global Digital Interconnect GIO[7:0] GOO[7:0]

Figure 1. Digital System Block Diagram

The Analog System

The Analog System is composed of 12 configurable blocks, each comprised of an opamp circuit allowing the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the more common EZ-Color analog functions (most available as user modules) are listed below.

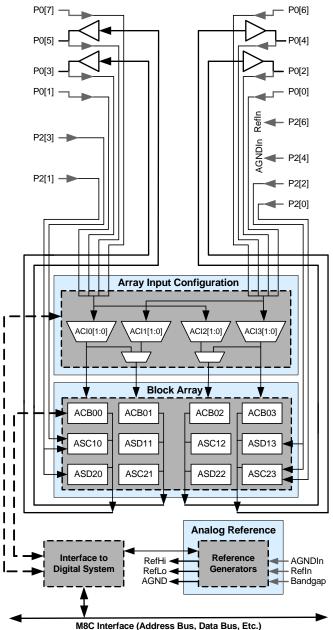
- Analog-to-digital converters (up to 4, with 6- to 14-bit resolution, selectable as Incremental, Delta Sigma, and SAR)
- Filters (2, 4, 6, or 8 pole band-pass, low-pass, and notch)
- Amplifiers (up to 4, with selectable gain to 48x)
- Instrumentation amplifiers (up to 2, with selectable gain to 93x)
- Comparators (up to 4, with 16 selectable thresholds)
- DACs (up to 4, with 6- to 9-bit resolution)
- Multiplying DACs (up to 4, with 6- to 9-bit resolution)
- High current output drivers (four with 40 mA drive as a core resource)
- 1.3 V reference (as a System resource)

CY8CLED16

- DTMF Dialer
- Modulators
- Correlators
- Peak Detectors
- Many other topologies possible

Analog blocks are provided in columns of three, which includes one continuous time (CT) and two switched capacitor (SC) blocks, as shown in the figure below.

Figure 2. Analog System Block Diagram





Additional System Resources

System resources, some of which have been previously listed, provide additional capability useful to complete systems. Resources include a multiplier, decimator, switch mode pump, low-voltage detection, and power-onreset (POR). Statements describing the merits of each system resource are presented below.

- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks can be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.
- Multiply accumulate (MAC) provides fast 8-bit multiplier with 32-bit accumulate, to assist in general math and digital filters.

- The decimator provides a custom hardware filter for digital signal, processing applications including the creation of Delta Sigma ADCs.
- The I²C module provides 100 and 400 kHz communication over two wires. Slave, master, and multi-master modes are all supported.
- Low-voltage-detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced power on reset (POR) circuit eliminates the need for a system supervisor.
- An internal 1.3-voltage reference provides an absolute reference for the analog system, including ADCs and DACs.
- An integrated switch-mode pump (SMP) generates normal operating voltages from a single 1.2-V battery cell, providing a low cost boost converter.

EZ-Color Device Characteristics

Depending on your EZ-Color device characteristics, the digital and analog systems can have 16, 8, or 4 digital blocks and 12, 6, or 4 analog blocks. The following table lists the resources available for specific EZ-Color device groups. The device covered by this data sheet is shown in the highlighted row of the table.

Table 1. EZ-Color Device Characteristics

Part Number	LED Channels	Digital I/O	Digital Rows	Digital Blocks	Analog Inputs	Analog Outputs	Analog Columns	Analog Blocks	SRAM Size	Flash Size	CapSense
CY8CLED02	2	16	1	4	8	0	2	4	256 Bytes	4K	No
CY8CLED04	4	56	1	4	48	2	2	6	1K	16K	Yes
CY8CLED08	8	44	2	8	12	4	4	12	256 Bytes	16K	No
CY8CLED16	16	44	4	16	12	4	4	12	2K	32K	No

Getting Started

The quickest way to understand the device is to read this data sheet and then use the PSoC Designer Integrated development environment (IDE). This data sheet is an overview of the EZ-Color integrated circuit and presents specific pin, register, and electrical specifications. For in depth information, along with detailed programming information, see the Technical Reference Manual for this PSoC device.

For up-to-date ordering, packaging, and electrical specification information, see the latest device data sheets on the web at http://www.cypress.com.

Application Notes

Cypress application notes are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

PSoC Development Kits are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops), which is available online via www.cypress.com, covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

Certified PSoC consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC consultant go to the CYPros Consultants web site.

Solutions Library

Visit our growing library of solution focused designs. Here you can find various application designs that include firmware and hardware design files that enable you to complete your designs quickly.

Technical Support

Technical support – including a searchable Knowledge Base articles and technical forums – is also available online. If you cannot find an answer to your question, call our Technical Support hotline at 1-800-541-4736.



Development Tools

PSoC Designer[™] is the revolutionary integrated design environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
- □ Hardware and software I²C slaves and masters
- □ Full-speed USB 2.0
- Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are analog-to-digital converters (ADCs), digital-to-analog converters (DACs), amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this lets you to use more than 100 percent of PSoC's resources for an application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also lets you to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer.

In-Circuit Emulator

A low-cost, high-functionality in-circuit emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24 MHz) operation.



Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed-function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and lowering inventory costs. These configurable resources, called PSoC blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is:

- 1. Select user modules.
- 2. Configure user modules.
- 3. Organize and connect.
- 4. Generate, verify, and debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called "user modules." User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a pulse with modulator (PWM) user module configures one or more digital PSoC blocks, one for each eight bits of resolution. Using these parameters, you can establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All of the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These user module datasheets explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information that you may need to successfully implement your design.

Organize and Connect

Build signal chains at the chip-Level by interconnecting user modules to each other and the I/O pins. Perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, perform the "Generate Configuration Files" step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides APIs with high-level functions to control and respond to hardware events at run time, and interrupt service routines that you can adapt as needed.

A complete code development environment lets you to develop and customize your applications in C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's Debugger (accessed by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full-speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer. It lets you to define complex breakpoint events that include monitoring address and data bus values, memory locations, and external signals.



Pin Information

Pinouts

The CY8CLED16 device is available in three packages which are listed and illustrated in the following tables. Every port pin (labeled with a "P") is capable of Digital I/O. However, Vss, V_{DD}, SMP, and XRES are not capable of Digital I/O.

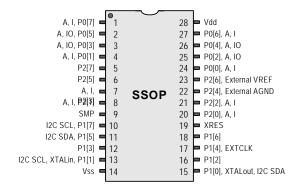
28-Pin Part Pinout

Table 2. 28-Pin Part Pinout (SSOP)

No. Digital Analog Name Description 1 I/O I P0[7] Analog column mux input. 2 I/O I/O P0[5] Analog column mux input and column output.	Pin	Ту	ре	Pin	-			
2 I/O I/O P0[5] Analog column mux input and column output. 3 I/O I/O P0[3] Analog column mux input and column output. 4 I/O I P0[1] Analog column mux input and column output. 5 I/O P2[7] 6 I/O P2[5] 7 I/O I P2[3] Direct switched capacitor block input. 8 I/O I P2[1] Direct switched capacitor block input. 9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I²C serial clock (SCL). 11 I/O P1[5] I²C serial data (SDA). 12 I/O P1[3] 13 I/O P1[1] Crystal (XTALout), I²C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[2] Crystal (XTALout), I²C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] optional external clock input (EXTCLK). 18 </th <th></th> <th>Digital</th> <th>Analog</th> <th></th> <th>Description</th>		Digital	Analog		Description			
3I/OI/OPO[1]Analog column mux input and column output.4I/OIPO[1]Analog column mux input.5I/OP2[7]6I/OP2[5]7I/OIP2[3]8I/OIP2[1]9PowerSMPSwitch mode pump (SMP) connection to external components required.10I/OP1[7]I ² C serial clock (SCL).11I/OP1[5]I ² C serial data (SDA).12I/OP1[3]13I/OP1[1]Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ¹¹ .14PowerVssGround connection.15I/OP1[0]Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ¹¹ .16I/OP1[2]17I/OP1[4]optional external clock input (EXTCLK).18I/OP1[6]19InputXRESActive high external reset with internal pull-down.20I/OI21I/OP2[4]23I/OP2[4]24I/OI25I/OI/O26I/OI/O27I/OI27I/OI27I/OI20I/OP0[2]Analog column mux input.	1	I/O	I	P0[7]	Analog column mux input.			
4I/OIP0[1]Analog column mux input.5I/OP2[7]6I/OP2[5]7I/OIP2[3]8I/OIP2[1]9PowerSMPSwitch mode pump (SMP) connection to external components required.10I/OP1[7]I²C serial clock (SCL).11I/OP1[5]I²C serial data (SDA).12I/OP1[3]Crystal (XTALin), I²C serial clock (SCL), ISSP-SCLK ¹¹ .14PowerVssGround connection.15I/OP1[0]Crystal (XTALout), I²C serial data (SDA), ISSP-SDATA ^[1] .16I/OP1[2]17I/OP1[4]18I/OP1[6]19InputXRES Active high external reset with internal pull- down.20I/OIP2[0]21I/OP2[4]External analog ground (AGND).23I/OP2[4]External voltage reference (VREF).24I/OIP0[0]25I/OI/OP0[2]26I/OI/OP0[4]Analog column mux input.25I/OI/O26I/OI/OP0[6]Analog column mux input.26I/O26I/OI27I/OI28Analog column mux input.	2	I/O	I/O	P0[5]	Analog column mux input and column output.			
5 I/O P2[7] 6 I/O P2[5] 7 I/O I P2[5] 7 I/O I P2[5] 7 I/O I P2[1] Direct switched capacitor block input. 8 I/O I P2[1] Direct switched capacitor block input. 9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I ² C serial clock (SCL). 11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[1] Crystal (XTAL in), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTAL out), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] Driect switched capacitor block input (EXTCLK). 18 I/O P1[6] Direct switched capacitor block input. 19 Input XRES Active high external reset with internal pull-down. 20 I/O I P2[0] Direct switched capacitor block input. 21	3	I/O	I/O	P0[3]	Analog column mux input and column output.			
6 I/O P2[5] 7 I/O I P2[3] Direct switched capacitor block input. 8 I/O I P2[1] Direct switched capacitor block input. 9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I ² C serial clock (SCL). 11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[3] Crystal (XTAL in), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTAL out), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[0] Direct switched capacitor block	4	I/O	I	P0[1]	Analog column mux input.			
7 I/O I P2[3] Direct switched capacitor block input. 8 I/O I P2[1] Direct switched capacitor block input. 9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I ² C serial clock (SCL). 11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[3] 13 I/O P1[1] Crystal (XTAL in), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTAL out), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull-down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 23 I/O I P2[6] <td< td=""><td>5</td><td>I/O</td><td></td><td>P2[7]</td><td></td></td<>	5	I/O		P2[7]				
8 I/O I P2[1] Direct switched capacitor block input. 9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I ² C serial clock (SCL). 11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[3] I ² C serial data (SDA). 13 I/O P1[1] Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] P1[6] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] P1[0] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I <td< td=""><td>6</td><td>I/O</td><td></td><td>P2[5]</td><td></td></td<>	6	I/O		P2[5]				
9 Power SMP Switch mode pump (SMP) connection to external components required. 10 I/O P1[7] I ² C serial clock (SCL). 11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[3] I ² C serial data (SDA). 13 I/O P1[1] Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] P1[6] 17 I/O P1[6] P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 23 I/O P2[4] External analog ground (AGND). 23 23 I/O P2[6]<	7	I/O	I	P2[3]	Direct switched capacitor block input.			
Image: start of the sector	8	I/O	I	P2[1]	Direct switched capacitor block input.			
11 I/O P1[5] I ² C serial data (SDA). 12 I/O P1[3] 13 I/O P1[1] Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ¹¹ . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 23 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input. <td>9</td> <td>Po</td> <td>wer</td> <td>SMP</td> <td>Switch mode pump (SMP) connection to external components required.</td>	9	Po	wer	SMP	Switch mode pump (SMP) connection to external components required.			
12 I/O P1[3] 13 I/O P1[1] Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 23 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input.	10	I/O		P1[7]	I ² C serial clock (SCL).			
13 I/O P1[1] Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] . 14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 18 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] Direct switched capacitor block input. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I P0[6] Analog co	11	I/O		P1[5]	I ² C serial data (SDA).			
14 Power Vss Ground connection. 15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input.	12	I/O		P1[3]				
15 I/O P1[0] Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] . 16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input. 27 I/O I P0[6] Analog column mux input.	13	I/O		P1[1]	Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] .			
16 I/O P1[2] 17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	14	Po	wer	Vss				
17 I/O P1[4] optional external clock input (EXTCLK). 18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	15	I/O		P1[0]	Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] .			
18 I/O P1[6] 19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input. 27 I/O I P0[6] Analog column mux input.	16	I/O		P1[2]				
19 Input XRES Active high external reset with internal pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	17	I/O		P1[4]	optional external clock input (EXTCLK).			
pull- down. 20 I/O I P2[0] Direct switched capacitor block input. 21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input. 27 I/O I P0[6] Analog column mux input.	18	I/O		P1[6]				
21 I/O I P2[2] Direct switched capacitor block input. 22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	19	Inj	out	XRES				
22 I/O P2[4] External analog ground (AGND). 23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	20	I/O	I	P2[0]	Direct switched capacitor block input.			
23 I/O P2[6] External voltage reference (VREF). 24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	21	I/O	I	P2[2]	Direct switched capacitor block input.			
24 I/O I P0[0] Analog column mux input. 25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	22	I/O		P2[4]	External analog ground (AGND).			
25 I/O I/O P0[2] Analog column mux input and column output. 26 I/O I/O P0[4] Analog column mux input and column output. 27 I/O I P0[6] Analog column mux input.	23	I/O		P2[6]	External voltage reference (VREF).			
26 I/O PO[4] Analog column mux input and column output. 27 I/O I PO[6] Analog column mux input.	24	I/O	I	P0[0]	Analog column mux input.			
27 I/O I P0[6] Analog column mux input.	25	I/O	I/O	P0[2]	Analog column mux input and column output			
	26	I/O	I/O	P0[4]	Analog column mux input and column output			
28 Power V _{DD} Supply voltage.	27	I/O	Ι		Analog column mux input.			
	28	Po	wer	V _{DD}	Supply voltage.			

LEGEND: A = Analog, I = Input, and O = Output.

Figure 3. 28-Pin Device



Note

1. These are the ISSP pins, which are not High Z at POR.



Table 3. 48-Pin Part Pinout (QFN)^[2]

Pin No.	Ty		Pin Name	Description				
	Digital	Analog		Direct quitched conseiter block input				
1	1/O 1/O		P2[3]	Direct switched capacitor block input.				
		I	P2[1]	Direct switched capacitor block input.				
3	I/O		P4[7]					
4	I/O		P4[5]					
5	I/O		P4[3]					
6	I/O		P4[1]					
7	Po	wer	SMP	Switch mode pump (SMP) connection to external components required.				
8	I/O		P3[7]					
9	I/O		P3[5]					
10	I/O		P3[3]					
11	I/O		P3[1]					
12	I/O		P5[3]					
13	I/O		P5[1]					
14	I/O		P1[7]	I ² C serial clock (SCL).				
15	I/O		P1[5]	I ² C serial data (SDA).				
16	I/O		P1[3]					
17	I/O		P1[1]	Crystal (XTALin), I ² C serial clock (SCL), ISSP-SCLK ^[1] .				
18	Po	wer	Vss	Ground connection.				
19	I/O		P1[0]	Crystal (XTALout), I ² C serial data (SDA), ISSP-SDATA ^[1] .				
20	I/O		P1[2]					
21	I/O		P1[4]	optional external clock input (EXTCLK).				
22	I/O		P1[6]					
23	I/O		P5[0]					
24	I/O		P5[2]					
25	I/O		P3[0]					
26	I/O		P3[2]					
27	I/O		P3[4]					
28	I/O		P3[6]					
29	Inp	out	XRES	Active high external reset with internal pull-down.				
30	I/O		P4[0]					
31	I/O		P4[2]					
32	I/O		P4[4]					
33	I/O		P4[6]					
34	I/O	I	P2[0]	Direct switched capacitor block input.				
35	I/O	I	P2[2]	Direct switched capacitor block input.				
36	I/O		P2[4]	external analog ground (AGND).				
37	I/O		P2[6]	external voltage reference (VREF).				
38	I/O	I	P0[0]	Analog column mux input.				
39	I/O	I/O	P0[2]	Analog column mux input and column output.				
40	I/O	I/O	P0[4]	Analog column mux input and column output.				
41	I/O	I	P0[6]	Analog column mux input.				
42	Po	wer	V _{DD}	Supply voltage.				
43	I/O	1	P0[7]	Analog column mux input.				
44	I/O	I/O	P0[5]	Analog column mux input and column output.				
45	I/O	I/O	P0[3]	Analog column mux input and column output.				
46	I/O	1/0	P0[1]	Analog column mux input and column output.				
47	I/O		P2[7]					
48	I/O		P2[5]					
-10	1/0		' ^{2[} 2]	l				

Figure 4. 48-Pin Device

P2[5] P2[7] P2[7] P0[1], A, I P0[3], A, IO P0[5], A, IO P0[4], A, I P0[4], A, I P0[4], A, IO P0[2], A, IO P0[0], A, I P2[6], External VREF A, I, P2[3] P4[7] P2[4], External AGND P2[2], A, I 34 P2[0], A, I P4[5] 33 🗖 P4[6] **=** 4 32 **P**4[4] P4[3] 5 P4[1] MLF 31 **=** 30 **=** P4[2] **-**6 SMP (Top View) P4[0] 7 29 **XRES** 28 **P**3[6] 27 **P**3[4] 8 P3[7] XRES **9**9 **1**10 **1**11 P3[5] P3[3] 26 P3[2] P3[1] P5[3] **■**12<u></u> 20 15 91 5 $^{\infty}$ 4 61 22 21 23 ñ ī ì 'n P5[1] P5[1] P2C SCL, P1[7] P1[3] P2C SCL, XTALIn, P1[1] P2C SDA, XTALout, P1[0] P2C SDA, XTALout, P1[0] P1[6] P5[0] P5[2]

LEGEND: A = Analog, I = Input, and O = Output. Note

 The center pad on the QFN package should be connected to ground (Vss) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floated and not connected to any other signal.



Register Reference

Register Conventions

Abbreviations Used

The register conventions specific to this section are listed in the following table.

Convention	Description							
R	Read register or bit(s)							
W	Write register or bit(s)							
L	Logical register or bit(s)							
С	Clearable register or bit(s)							
#	Access is bit specific							

Register Mapping Tables

This chapter lists the registers of the CY8CLED16 EZ-Color device.

The device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks, Bank 0 and bank 1. The XOI bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XOI bit is set the user is in Bank 1.

Note In the following register mapping tables, blank fields are reserved and should not be accessed.



Table 4. Register Map Bank 0 Table: User Space

Internet Addr (Mate) Addr (Mate)		· ·	r	able: User a				1				
PHTOSE OI NV DBBSDOP1 41 WV ASC10CR1 61. MV ROZIN C1 MV PHTOSE OL NV DBBSDOP 42 RV ASC10CR3 81 RV ROZINTO C3 RV PHTOSE OL NV DBBSTDPA 42 Status 84 Status RV ROZINTO C3 RVV PHTUE OS RV DBBSTDPA 44 R ASD11CR1 55 RV ROZINTO C3 RVV PHTOSE OS RVV DBBSTDPA C4 RV ASD11CR1 65 RVV ROZINTO C3 RVV PHTOSE OS RVV DESEDDPA 64 RV ASD11CR2 80 RVV ROZINTO C6 RV PHTOSE OC RV DESEDDPA 64 RV ASD12CR2 80 RVV ROZINTO C6 RV PHTOSE OC RVV	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Acces	Name	Addr (0,Hex)	Acces
PRITOM 002 NV Description 42 FW ASC/UCK BU RVV ROUNC C.2 RVV PRITOM 64 NV Description 44 N ASC/UCK 83 RVV ROULTI C.3 RV PRITINE 0.4 NV Description 44 N ASD/UCK 84 RVV ROUNC C.3 RVV PRITOM 0.6 NV Description 44 RV ASD/UCK 84 RVV ROUNC C.3 RVV PRITOM 0.6 NV DEscription 44 RV ASD/UCK 84 RVV ROUNC C.3 RVV PRITOM 0.6 NV DEscription 44 RV ASD/UCK 84 RVV ROUNC C.3 RVV PRITOM 0.6 RVV DEscription 44 RV ASD/UCK 84 RVV ROUNC C.2 RVV PRITOM 0.6												
PHYDRA PHYDR03NW080000448ASC110004NWNU0300110C3NWNU	PRT0IE	01	RW	DBB20DR1	41	W	ASC10CR1	81	RW	RDI2SYN	C1	RW
PHYT166484848485017/6384.87.NDD.17.64.87.PHYT1606FWDB6270H246RWASD17CR286RWNDD2006387.PHT150807RWDB6270F248RWASD17CR286RWDD207167.77.78.PHT26E06RWDB6220F048RWASD17CR288RWR0181C77.78.PH725E06RWDC6220F148RWASD17CR288.RWR0185C60.87.PH725E06RWDC6220F149.RWASD17CR288.RWR0185C67.87.PH73606RWDC6220F147.RWASD17CR288.RWR0187C67.87.PH73607RWDC6220F147.RWASD17CR287.RWR018767.87.PH73607RWDC6220F247.RWASD17CR287.RWR018767.87.PH73617RWDC6220F247.RWASD17CR287.RWR018767.87.PH73617RWDC6220F248.RWASD17CR288.RWR018767.87.PH73617RWDC6220F218.RWASD17CR288.RWR018776.76.PH73617RW <td< td=""><td>PRT0GS</td><td>02</td><td>RW</td><td>DBB20DR2</td><td>42</td><td>RW</td><td>ASC10CR2</td><td>82</td><td>RW</td><td>RDI2IS</td><td>C2</td><td>RW</td></td<>	PRT0GS	02	RW	DBB20DR2	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PHYT16506R.WDBBC7DM46WABD17CR248.RWADD7CBODRODC5.KBPHYT15007RWDBBC270K347RWASD17CR287RWRDC5.RWPHYT26708RWDC222DR148RWASD17CR388RWRDDS7NC5.RWPHYZ560.ARWDC222DR148WASD17CR188RWRDDS7NCA.RWPHYZ560.ARWDC222DR148RWASD17CR188RWRDDS7NCA.RWPHYZ560.CRWDC222DR148RWASD17CR188RWRDDS7NCA.RWPHYD670.CRWDC222DR148RWASD17CR188RWRDDS7NCA.RWPHYD70.CRWDC222DR148RWASD17CR188RWRDDS7NCA.RWPHYD70.CRWCC22DR146RWASD17CR188RWRDDS7NCC22DR1RWPHYD71.CRWRWDC22DR146RWASD17CR188RWRDDS7NCC22DR1RWPHYD71.CRWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRSD17CR1RWRS	PRT0DM2	03	RW	DBB20CR0	43	#	ASC10CR3	83	RW	RDI2LT0	C3	RW
PHYTGM266RW0B02/06247aASD1(R2)89RWDODD()0.0MMPHYT2M005RW0D82DN047aASD12CN083RWDODD()07MPHYZBC00RW0C522DN140WASD12CN183RWRDDISK0.0RWPHYZBC00RW0C522DN240WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN240WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN285RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN285RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD22CN190RWRDDISK0.0RWPHYZBC10RW0C522DN180WASD22CN190RWRDUSK0.0RWPHYZBC10RW0C522DN180RWASD22CN190RWRDUSK0.0RWPHYZBC10RW0C522DN150RWASD22CN190RWRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSK	PRT1DR	04	RW	DBB21DR0	44	#	ASD11CR0	84	RW	RDI2LT1	C4	RW
PHYTGM266RW0B02/06247aASD1(R2)89RWDODD()0.0MMPHYT2M005RW0D82DN047aASD12CN083RWDODD()07MPHYZBC00RW0C522DN140WASD12CN183RWRDDISK0.0RWPHYZBC00RW0C522DN240WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN240WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN284RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN285RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD12CN285RWRDDISK0.0RWPHYZBC00RW0C522DN140WASD22CN190RWRDDISK0.0RWPHYZBC10RW0C522DN180WASD22CN190RWRDUSK0.0RWPHYZBC10RW0C522DN180RWASD22CN190RWRDUSK0.0RWPHYZBC10RW0C522DN150RWASD22CN190RWRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSKRDUSK	PRT1IE	05	RW	DBB21DR1	45	W	ASD11CR1	85	RW	RDI2RO0	C5	RW
PHT1DE PT RW DBE2/CR0 4/r F ABDIT/CR0 8/r RW PCT2/P B RW DD52/D RW DD52/D RW DD52/D RW RD52/R RW RD	PRT1GS					RW			RW			
PHT2DE06NWDOBUZDNO46NASC1CKN88NWNDDNI05.80NWPHT2DE06NWDOBUZDNC4.4NWASC1CKN8.4NWNDDNI05NWPHT2DM206NWDOBUZDNC4.4NWASC1CKN8.4NWNDDNI05NWPHT2DM200RWDOBUZDNC4.6NASD1SCN8.6NWNDDNI05NWPHT3DM20CRWDOBUZDNC4.6NASD1SCN8.6NWNDDNI05NWPHT3DS0CRWDOBUZDNC4.7NASD1SCN8.7NWNDDNI05NWNDDNINWNDDNINDDNINWNDDNI <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td>110121101</td> <td></td> <td></td>										110121101		
PHT2GE 09 NW DOB220FI 49 W ASC12CH2 84 RW ROUSS C PM PHT2GS 06 NW DOB220F0 44 PW ASC12CH2 84 RW ROUSS C RW ROUSS CB RW ROUSS RU		-								PDI2DI		DW/
PRT25M2 OA NW DCR2207C2 4A RW ASC12CR3 BA PK ROUST CA FW PRT3DE OC NW DCR23070 4C # ASD13CR0 BC RW ROIST-IC CC RW PRT3DE OC NW DCR230781 4D W ASD13CR2 BE RW ROISO1 CC RW PRT3DK OF RW DCR230782 4E RW ASD13CR2 BE RW ROISO1 CC RW PRT3DK OF RW DCR230782 4E RW ASD13CR2 BE RW CULR, PF D0 RW PRT3DK2 OF RW DCR230781 45 W ASD20CR2 92 RW CULR, PF D3 RW PRT4DK1 13 RW DB831DR0 54 # ASD20CR3 93 RW MCS2R4 94 RW PRT505 16 RW <												
PRT2DR 06 RW DCh22CR0 46 # ASC12CR3 86 RW RDIGAT CB RW PRTSDR OC RW DCh22OR0 46 # ASD12CR1 8C RW RDIGNO CD RW PRTSDS OF RW DCh22OR1 4D W ASD12CR1 8E RW RDIGNO CD RW PRTSDS OF RW DCh22OR0 4F P ASD12CR3 8F RW RDIGNO CF RW PRTAINE 10 RW DEBSDORD 50 # ASD20CR1 91 RW CLCR DB RW PRTAINE 13 RW DBBSDORD 51 W ASD20CR1 93 RW MX DR RW RXC1R0 73 RW ASD20CR1 93 RW MX DR RW RXC1R0 77 RW ASD20CR1 93 RW MXC1R0 75 RW												
PHY3DE OC NM DCR230R0 4/C # ASD13CH0 B/C R/M RODRACT CC PM PHY3DE OD NW DCR230R2 4/E R/W ASD13CH2 8/E R/W RODRACO CF R/W PHY3DM2 OF R/W DCR230R2 4/E R/W ASD13CH2 8/E R/W RODRACO CF R/W RODRACO CF R/W RODRACO CF R/W RODRACO CF R/W RODRACO SSD # ASD13CH2 8/E R/W												
PHYSGE DD PW DCB230R1 4D W ABD13CR2 4E RW ABD13CR2 6E RW RDBROD CD RW PHYSGE 0F RW DDB200R0 5G RW DDB200R1 5F RW DDB200R1 5F RW DDR RW CP D RW PHYALR 11 RW DBB300R1 51 W ABD20CR1 91 RW STC_PP D1 RW PHYALR 12 RW DBB300R0 53 # ABD20CR2 32 RW DDZ T RW PDR AD 4 # ABD20CR2 33 RW PDX PD< AD		-						-				
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PHTADR OF RW DCB23CR0 4F # ASD13CR3 6F RW CF P PHTADR 10 RW DBB30DR1 51 W ASD20CR0 90 RW DR1 RW PHTAGS 12 RW DBB30DR2 52 RW ASD20CR2 92 RW DD RW PHTAGS 13 RW DBB30DR0 53 # ASD20CR2 92 RW DD RW PHTAGS 14 RW DBB31DR1 55 RW ASD20CR2 94 RW NWR-PP DA RW PHTSOR 16 RW DBB31DR1 55 RW ASC21CR2 06 RW NW2.PP DA RW PHTGOR 16 RW DBB31DR1 55 RW ASC21CR2 06 RW NU2.PP DA RW PHTGOR 16 RW DDB31DR1 55 RW ASC21CR2 06	PRT3IE	0D	RW	DCB23DR1	4D	W	ASD13CR1	8D	RW	RDI3RO0	CD	RW
PRTADE 10 RW DBBS30R0 80 # ADD20CR 90 RW CUR.PP D0 RW PRTAGE 12 RW DBB300R2 82 RW ADD20CR2 92 RW DB DB DB RW DD DD DB RW DB DB RW DB RW DB DB RW DB DB RW DD DD	PRT3GS	0E	RW	DCB23DR2	4E	RW	ASD13CR2	8E	RW	RDI3RO1	CE	RW
PRTAGE 11 RW OBB300R1 91 RW AD200CR1 91 RW STR.PP D1 RW PRTAGS 12 RW OBB30CR0 53 # AD200CR3 92 RW DD2 D PRTADR 13 RW OBB30CR0 53 # AD200CR3 93 RW MVP.PP D3 RW PRTSDR 16 RW OBB30CR0 53 # ASC21CR1 95 RW MVP.PP D4 RW PRTSDR 15 RW OBB30CR0 57 # ASC21CR3 97 RW E2C.DR D7 # PRTSDR 15 RW OBB30CR0 56 # ASD22CR3 96 RW RC2.DR D8 RW RC3.DR D8 RW AD22CR3 96 RW NT_CLR3 D0 RW RC1.R3 D0 RW RC1.R3 D0 RW RC1.R3 D0 RW RC1.R3	PRT3DM2	0F	RW	DCB23CR0	4F	#	ASD13CR3	8F	RW		CF	
PRTAGE 11 RW OBB300R1 91 RW AD200CR1 91 RW STR.PP D1 RW PRTAGS 12 RW OBB30CR0 53 # AD200CR3 92 RW DD2 D PRTADR 13 RW OBB30CR0 53 # AD200CR3 93 RW MVP.PP D3 RW PRTSDR 16 RW OBB30CR0 53 # ASC21CR1 95 RW MVP.PP D4 RW PRTSDR 15 RW OBB30CR0 57 # ASC21CR3 97 RW E2C.DR D7 # PRTSDR 15 RW OBB30CR0 56 # ASD22CR3 96 RW RC2.DR D8 RW RC3.DR D8 RW AD22CR3 96 RW NT_CLR3 D0 RW RC1.R3 D0 RW RC1.R3 D0 RW RC1.R3 D0 RW RC1.R3	PRT4DR	10	RW	DBB30DR0	50	#	ASD20CR0	90	RW	CUR PP	D0	RW
PRT45S 12 RW DBB300R2 12 RW ASD20CR2 92 RW DZ P PRT4DM2 13 RW DBB300R0 63 # ASD20CR3 93 RW IDX.PP D3 RW PRT5GS 14 RW DBB310R2 66 RW ASC21CR1 95 RW IVV.PP D4 RW PRT5GS 16 RW DBB310R2 66 RW ASC21CR3 95 RW IVV.PP D4 RW PRT5GS 16 RW DBB310R2 56 RW ASC21CR3 95 RW IZC_CR D7 # PRT5DR 18 RW DCB320R1 50 W ASD22CR3 98 RW INT_CLR3 DA # PRT6DR 18 RW DCB330R1 50 # ASD22CR3 98 RW INT_CLR3 DD RW PRT6DR 11 RW DCB330R0 5C <td></td>												
PRTADIZ 13 RW DBB30CR0 53 # ABD20CR3 93 RW DIX_PP D3 RW PRTSDE 16 RW DBB310R1 56 W ASC21CR1 96 RW MVM_PP D5 RW PRTSGS 16 RW DBB310R1 56 W ASC21CR1 96 RW MVM_PP D5 RW PRTSDS 16 RW DBB310R1 56 RW ASC21CR3 97 RW 102_CSC D5 RW PRTSDS 18 RW DCB32DR1 50 W ASD22CR1 90 RW 102_CMSC D6 RW PRTSDR 18 RW DCB32DR1 50 # ASD22CR3 98 RW NT_CLR1 D8 RW PRTSDR 18 RW DCB32DR1 50 # ASD22CR3 98 RW NT_CLR2 DC RW PRTSDR 12 RW DCB32D										•		
PRTOR 14 RW DBB310R1 54 # ASC21CR0 94 RW NW, PP DA RW PRTSIG 15 RW DBB310R1 55 W ASC21CR1 95 RW MW DCC-CF0 DB RW PRTSGM 17 RW DBB310R2 56 W ASC21CR2 96 RW UC_CF0 DB RW PRTSGM 18 RW DCB32DR1 58 # ASC21CR2 98 RW IZC_MSCR D3 RW PRTGS 1.4 RW DCB32DR1 58 # ASD22CR1 98 RW INT_CLR1 DB RW PRTGS 1.4 RW DCB32DR1 50 W ASC23CR1 90 RW INT_CLR1 DB RW PRTOR 16 RW DCB33DR1 50 W ASC23CR1 90 RW INT_MSK1 DE RW NTT_MSK3 DE RW NTT												D\//
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PRTBDR 16 RW DCB32DR1 59 # ASD22CR0 69 RW ICC_DR D8 RW PRTGE 19 RW DCB32DR1 59 W ASD22CR1 69 RW IRC_DR DA RW IRC_DR DA RW INT_CLR0 DA RW PRTGR 18 RW DCB32CR0 56 # ASD22CR2 9A RW INT_CLR1 DB RW PRTTG 1C RW DCB33DR1 5D W ASC32R0 9C RW INT_CLR2 DC RW PRTTG 1E RW DCB33DR2 5E RW ASC32R2 9E RW INT_MSG2 DF RW DBB000R0 20 # AMX_IN 60 RW ASC32R2 9E RW INT_MSG2 DF RW DBB000R0 23 # AF_C_CR 63 RW AA3 RES_WOT E3 W				-								RW
PRTBIE 19 RW DCB32DR1 59 W ASD22CR1 99 RW UZ_MSCR 09 # PRT6GS 1A RW DCB32DR2 5A RW ASD22CR2 9A RW INT_CLR0 DA RW PRT6DM2 1B RW DCB32DR0 5C # ASD22CR3 9B RW INT_CLR2 DC RW PRT7DR 1C RW DCB33DR1 5D W ASC22CR1 9D RW INT_CLR3 DD RW PRT70S 1E RW DCB33DR1 5D W ASC23CR3 9E RW INT_MSK3 DE RW PRT70S 1F RW DCB33DR0 5C RW ASC23CR3 9F RW INT_MSK3 DE RW DB800DR1 21 W 61 RW AS AS DEC_DH ES RC DB800DR1 22 R/W AF GS R	PRT5DM2	17	RW	DBB31CR0	57	#	ASC21CR3	97	RW	I2C_SCR	D7	#
PRT6GS 1A RW DCB32DP2 5A RW ASD22CR3 9A RW INT_CLR DA RW PRT6DM2 1B RW DCB33DR0 5C # ASD22CR3 9B RW INT_CLR1 DB RW PRT7B 1C RW DCB33DR1 5D W ASC23CR1 9B RW INT_CLR3 DD RW PRT716 1E RW DCB33DR2 5E RW ASC23CR1 9B RW INT_MSK3 DD RW PRT70X 1F RW DCB33DR2 3E RW ASC23CR3 9F RW INT_MSK3 DD RW DB8000R1 21 W CB33DR2 6E RW ASC23CR3 9F RW INT_MSK3 EI RW DB8000R1 21 W CB33DR2 6R W ASC3CR3 9F RW INT_LRX RI RW DB500CR0 SG RW ASC32DR2	PRT6DR	18	RW	DCB32DR0	58	#	ASD22CR0	98	RW	I2C_DR	D8	RW
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IPRT7DR 1C RW DCB33DR0 SD # ASC23CR1 9C RW INT_CLR2 DC RW PRT7IE 1D RW DCB33DR1 SD W ASC23CR1 9D RW INT_CLR3 DD RW PRT70S 1E RW DCB33DR2 SE RW ASC23CR2 9E RW INT_MSK3 DE RW DB800DR0 20 # AMX_IN 60 RW ASC23CR3 9F RW NT_MSK3 DE RW DB800DR0 20 # AMX_IN 60 RW A3 RT_MSK3 E1 RW DB800DR1 21 W 662 RW A3 REs_WDT E3 W DB800DR0 23 # ARF_CR 65 # A5 DEC_DH E4 RC DB801DR1 25 W CMP_CR1 66 RW A6 DEC_CN E6 RW	PRT6GS	1A	RW	DCB32DR2	5A	RW	ASD22CR2	9A	RW	INT_CLR0	DA	RW
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DBB00CR0 23 # ARF_CR 63 RW A3 RES_WDT E3 W DBB01DR0 24 # CMP_CR0 64 # A4 DEC_DH E4 RC DB801DR1 25 W ASY_CR 65 # A4 DEC_DL E5 RC DB801DR2 26 RW CMP_CR1 66 RW A6 DEC_DL E5 RC DB801DR2 26 RW CMP_CR1 66 RW A6 DEC_DL E5 RC DC802DR1 29 W 67 A7 DEC_CR1 E7 RW DC802DR1 29 W 68 MUL1_DH A8 W MUL0_DH EA R DC802DR2 2A RW 66 MUL1_DL AA R MUL0_DL EA R DC603DR0 2C # TMP_DR1 6D RW ACC1_DR1 AC RW ACC0_DR2 </td <td>DBB00DR1</td> <td>21</td> <td>W</td> <td></td> <td>61</td> <td></td> <td></td> <td>A1</td> <td></td> <td>INT_MSK1</td> <td>E1</td> <td>RW</td>	DBB00DR1	21	W		61			A1		INT_MSK1	E1	RW
DBB01DR0 24 # CMP_CR0 64 # A4 DEC_DH E4 RC DBB01DR1 25 W ASY_CR 65 # A5 DEC_DL E5 RC DBB01CR0 27 # 67 A6 DEC_CR1 E6 RW DB801CR0 27 # 67 A7 DEC_CR1 E7 RW DC802DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DC802DR1 29 W 69 MUL1_H AA R MUL0_DH EA R DC802DR0 28 # 68 MUL1_DH AA R MUL0_DH EA R DC803DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EB R DC803DR2 2E RW TMP_DR3 6F RW ACC1_DR3 AE RW ACC0_DR3 <td>DBB00DR2</td> <td>22</td> <td>RW</td> <td></td> <td>62</td> <td></td> <td></td> <td>A2</td> <td></td> <td>INT_VC</td> <td>E2</td> <td>RC</td>	DBB00DR2	22	RW		62			A2		INT_VC	E2	RC
DBB01DR1 25 W ASY_CR 65 # AS DEC_DL E5 RC DBB01DR2 26 RW CMP_CR1 66 RW A6 DEC_CR0 E6 RW DBB01CR0 27 # 67 A7 DEC_CR1 E7 RW DC802DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DC802DR1 29 W 69 MUL1_DH A8 M MUL0_Y E9 W DC802DR2 2A RW 6A MUL1_DH AA R MUL0_DH EA R DC803DR0 2C # TMP_DR0 6C RW ACC1_DR0 AD RW ACC0_DR1 EC RW DC803DR1 2D W TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DC803DR0 2F # TMP_DR3 6F RW	DBB00CR0	23	#	ARF_CR	63	RW		A3		RES_WDT	E3	W
DBB01DR1 25 W ASY_CR 65 # A5 DEC_DL E5 RC DBB01DR2 26 RW CMP_CR1 66 RW A6 DEC_CR0 E6 RW DBB01CR0 27 # 67 A7 DEC_CR1 E7 RW DC802DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DC802DR1 29 W 69 MUL1_DL A8 W MUL0_U E9 W DC802DR1 29 W 6A MUL1_DL A8 R MUL0_DL E8 R DC803DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DC803DR1 2D W TMP_DR2 6E RW ACC1_DR0 AD RW ACC0_DR3 EE RW DC803DR0 2F # TMP_DR2 6F RW<	DBB01DR0	24	#	CMP CR0	64	#		A4		DEC DH	E4	RC
DBB01DR2 26 RW CMP_CR1 66 RW A6 DEC_CR0 E6 RW DBB01CR0 27 # 67 A7 DEC_CR1 E7 RW DCB02DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DCB02DR1 29 W 69 MUL1_Y A9 W MUL0_Y E9 W DCB02DR2 2A RW 6A MUL1_DL A8 R MUL0_DL E8 R DCB02DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 E8 R DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR0 AD RW ACC0_DR3 EE RW DCB03DR2 2E RW TMP_DR3 6F RW ACC1_DR3 AE RW ACC0_DR3 EE RW DB810DR0 30 # <t< td=""><td></td><td>25</td><td>W</td><td></td><td></td><td>#</td><td></td><td>A5</td><td></td><td></td><td>E5</td><td>RC</td></t<>		25	W			#		A5			E5	RC
DBB01CR0 27 # 67 A7 DEC_CR1 E7 RW DCB02DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DCB02DR1 29 W 69 MUL1_Y A9 W MUL0_Y E9 W DCB02DR2 2A RW 6A MUL1_DL A8 R MUL0_DL E8 R DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03DR2 2E RW TMP_DR3 6F RW ACC1_DR3 AE RW ACC0_DR3 EE RW DB810DR0 30 # ACB00CR3 70 RW RDIOR1 B0 RW F1 D D DB10DR1 31 <td< td=""><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></td<>												
DCB02DR0 28 # 68 MUL1_X A8 W MUL0_X E8 W DCB02DR1 29 W 69 MUL1_Y A9 W MUL0_X E8 W DCB02DR2 2A RW 6A MUL1_DH AA R MUL0_DL E9 W DCB02DR2 2A RW 6A MUL1_DL AB R MUL0_DL E8 R DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR2 AE RW ACC0_DR3 EE RW DCB03DR1 2D W TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR3 EE RW DCB03DR1 30 # ACB00CR1 71 RW RDI0SIN B1 RW AC20_DR2 EF RW												
DCB02DR1 29 W 69 MUL1_Y A9 W MUL0_Y E9 W DCB02DR2 2A RW 6A MUL1_DH AA R MUL0_DH EA R DCB02CR0 2B # 6B MUL1_DL AB R MUL0_DL EB R DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR2 AF RW ACC0_DR3 EE RW DCB03DR2 2E RW TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR2 EF RW DB810DR0 30 # ACB00CR3 70 RW RDIOSYN B1 RW F1 D DB810DR2 32 RW ACB00CR2 73 RW RDIOIS B2 RW F3 D									14/			
DCB02DR2 2A RW 6A MUL1_DH AA R MUL0_DH EA R DCB02CR0 2B # 6B MUL1_DL AB R MUL0_DL EB R DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR0 AD RW ACC0_DR0 ED RW DCB03DR1 2D W TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03DR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR3 EE RW DB810DR1 30 # ACB00CR3 70 RW RDI0R1 B0 RW F1 E B B RW F1 E F0 E F1 E E E												
DCB02CR0 2B # 6B MUL1_DL AB R MUL0_DL EB R DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR0 AD RW ACC0_DR0 ED RW DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR2 AF RW ACC0_DR2 EF RW DCB03CR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR2 EF RW DCB03DR0 30 # ACB00CR3 70 RW RDIORI B0 RW ACC0_DR2 EF RW DB810DR1 31 W ACB00CR1 71 RW RDI0S B1 RW F1 C DB DB DB B3 RW F3 C D							—	-				
DCB03DR0 2C # TMP_DR0 6C RW ACC1_DR1 AC RW ACC0_DR1 EC RW DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR0 AD RW ACC0_DR0 ED RW DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03DR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR3 EE RW DBB10DR0 30 # ACB00CR0 71 RW RDIOSYN B1 RW F1 D DBB10DR1 31 W ACB00CR1 72 RW RDIOIS B2 RW F1 D DBB10DR0 34 # ACB01CR3 74 <t< td=""><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></t<>												
DCB03DR1 2D W TMP_DR1 6D RW ACC1_DR0 AD RW ACC0_DR0 ED RW DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03DR2 2E # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR3 EE RW DB810DR0 30 # ACB00CR3 70 RW RDIORI B0 RW ACC0_DR2 EF RW DB810DR1 31 W ACB00CR0 71 RW RDIOSYN B1 RW F1 D DB810DR2 32 RW ACB00CR1 72 RW RDIOIS B2 RW F3 D DB810DR1 34 # ACB01CR3 74 RW RDIOR0 B5 RW F4 D DB811DR1 35 W ACB01CR2 77 RW RDIORO1	DCB02CR0	2B	#		6B		MUL1_DL	AB	R	MUL0_DL	EB	R
DCB03DR2 2E RW TMP_DR2 6E RW ACC1_DR3 AE RW ACC0_DR3 EE RW DCB03CR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR3 EF RW DBB10DR0 30 # ACB00CR3 70 RW RDIORI B0 RW ACC0_DR2 EF RW DBB10DR1 31 W ACB00CR0 71 RW RDIORI B0 RW F1 F1 F1 DBB10DR2 32 RW ACB00CR1 72 RW RDIOIS B2 RW F2 F3 DBB10DR2 33 # ACB01CR3 74 RW RDIOIT0 B3 RW F4 F4 F4 F5 F4 F5 F4 F5 F6 F6 F6 F6 F6 F6 F6 F8 F8 F6 F8 F8 F6 F8 F8	DCB03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCB03CR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR2 EF RW DBB10DR0 30 # ACB00CR3 70 RW RDIORI B0 RW F0 F0 DBB10DR1 31 W ACB00CR0 71 RW RDI0SYN B1 RW F1 F1 F2 F1 DBB10DR2 32 RW ACB00CR1 72 RW RDI0IS B2 RW F3 F3 F4 DBB10DR0 33 # ACB01CR3 74 RW RDI0IT0 B3 RW F4 F4 F5 F5 F5 F5 F5 F6 F6 F6 F6 F6 F6 F6 F8 F8 F8 F8 F8 F8 F8 F8 F6 F8 F8 F8 F6 F6 F8 F8 F8 F8 F8 F8 F8 F8 F8	DCB03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCB03CR0 2F # TMP_DR3 6F RW ACC1_DR2 AF RW ACC0_DR2 EF RW DBB10DR0 30 # ACB00CR3 70 RW RDIORI B0 RW F0 F0 DBB10DR1 31 W ACB00CR0 71 RW RDI0SYN B1 RW F1 F1 F1 DBB10DR2 32 RW ACB00CR1 72 RW RDI0IS B2 RW F2 F2 DBB10DR0 33 # ACB01CR3 74 RW RDI0IT0 B3 RW F3 F4 F4 F5 F5 F5 F5 F5 F5 F5 F5 F6 F6 F6 F6 F6 F6 F8 F6 F8 F8 F8 F6 F8 F8 F8 F8 F8 F6	DCB03DR2	2E	RW	TMP DR2	6E	RW	ACC1 DR3	AE	RW	ACC0 DR3	EE	RW
DBB10DR0 30 # ACB00CR3 70 RW RDIORI B0 RW F0 F0 DBB10DR1 31 W ACB00CR0 71 RW RDIOSYN B1 RW F1 F1 F2 F1 F2 F2 F2 F2 F3 F3 F3 F4 ACB00CR2 73 RW RDIOLTO B3 RW F4 F4 F4 F5 F4 F5 F4 F5 F5 F5 F6 F8 F6 F6 F8 F8 F6 F6 F6 F8 F9 F8 F9 F8 F9		2F	#		6F	RW		AF	RW	ACC0_DR2	EF	RW
DBB10DR1 31 W ACB00CR0 71 RW RDIOSYN B1 RW F1 I DBB10DR2 32 RW ACB00CR1 72 RW RDI0IS B2 RW F2 I DBB10CR0 33 # ACB00CR2 73 RW RDI0IT B3 RW F3 I DBB11DR0 34 # ACB01CR3 74 RW RDI0IT B4 RW F4 I DBB11DR1 35 W ACB01CR0 75 RW RDI0R00 B5 RW F6 I DBB11DR2 36 RW ACB01CR2 77 RW B7 CPU_F F7 RL DBB11DR2 36 RW ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 I I GE02CR2 F8					-							
DBB10DR2 32 RW ACB00CR1 72 RW RDI0IS B2 RW F2 I DBB10CR0 33 # ACB00CR2 73 RW RDI0IT B3 RW F3 I DBB11DR0 34 # ACB01CR3 74 RW RDI0LT1 B4 RW F4 I DBB11DR1 35 W ACB01CR0 75 RW RDI0R00 B5 RW F6 I DBB11DR1 35 W ACB01CR1 76 RW RDI0R01 B6 RW F6 I DBB11DR2 36 RW ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 I DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F4 I DCB12DR1 34 ACB02												
DBB10CR0 33 # ACB00CR2 73 RW RDIOLTO B3 RW F3 F3 DBB11DR0 34 # ACB01CR3 74 RW RDIOLT1 B4 RW F4 F4 F5 DBB11DR1 35 W ACB01CR0 75 RW RDIORO0 B5 RW F5 F5 DBB11DR2 36 RW ACB01CR2 77 RW RDIORO0 B5 RW F6 F6 F6 F6 F6 F6 F8 F9 F6 F8 F8 F9 F8 F9 F8 F												
DBB11DR0 34 # ACB01CR3 74 RW RDIoLT1 B4 RW F4 P4 DBB11DR1 35 W ACB01CR0 75 RW RDI0RO0 B5 RW F5 D DBB11DR2 36 RW ACB01CR1 76 RW RDI0RO1 B6 RW F6 D DBB11DR2 36 RW ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 CPU_F F7 RL DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F4 F8 CDCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW F4 F4 F4 F6 F8 F6	-											
DBB11DR1 35 W ACB01CR0 75 RW RDI0RO0 B5 RW F5 I DBB11DR2 36 RW ACB01CR1 76 RW RDI0RO1 B6 RW F6 I DBB11DR2 36 RW ACB01CR1 76 RW RDI0RO1 B6 RW F6 I DBB11CR0 37 # ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 I DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 I DCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW FA I DCB12DR2 3A RW ACB02CR2 7B RW RDI1LT0 BB RW FA I DCB13DR0<												
DBB11DR2 36 RW ACB01CR1 76 RW RDI0RO1 B6 RW F6 DBB11CR0 37 # ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 C DCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW FA C DCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW FA DCB12DR0 3B # ACB02CR2 7B RW RDI1TO BB RW FA DCB13DR0 3C # ACB03CR3 7C RW RDI1TO BB RW FC ID DCB13DR1 3D W ACB03CR0												
DBB11CR0 37 # ACB01CR2 77 RW B7 CPU_F F7 RL DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 E DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 E DCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW FA E DCB12DR2 3A RW ACB02CR2 7B RW RDI1LTO BB RW FA E DCB12DR0 3B # ACB02CR2 7B RW RDI1LTO BB RW FB E DCB13DR0 3C # ACB03CR3 7C RW RDI1LT1 BC RW FC FC E DCB13DR1 3D W ACB03CR0 7D RW RDI1RO0 BD RW FD FD FD	DBB11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DCB12DR0 38 # ACB02CR3 78 RW RDI1RI B8 RW F8 F8 DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 F9 DCB12DR2 3A RW ACB02CR1 7A RW RDI1SYN B9 RW FA F4 DCB12DR2 3A RW ACB02CR1 7A RW RDI1IS BA RW FA F4 DCB12DR0 3B # ACB02CR2 7B RW RDI1LT0 BB RW FB F5 DCB13DR0 3C # ACB03CR3 7C RW RDI1LT1 BC RW FC F0 DCB13DR1 3D W ACB03CR0 7D RW RDI1RO0 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RDI1RO1 BE RW CPU_SCR1 FE	DBB11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 P DCB12DR2 3A RW ACB02CR1 7A RW RDI1S BA RW FA FA DCB12DR2 3B # ACB02CR2 7B RW RDI1LTO BB RW FB FB DCB13DR0 3C # ACB03CR3 7C RW RDI1LTO BC RW FC FC DCB13DR1 3D W ACB03CR0 7D RW RDI1RO0 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RDI1RO1 BE RW CPU_SCR1 FE #	DBB11CR0	37	#	ACB01CR2	77	RW		B7	1	CPU_F	F7	RL
DCB12DR1 39 W ACB02CR0 79 RW RDI1SYN B9 RW F9 P DCB12DR2 3A RW ACB02CR1 7A RW RDI1IS BA RW FA D DCB12DR2 3B # ACB02CR2 7B RW RDI1LTO BB RW FB D DCB13DR0 3C # ACB03CR3 7C RW RDI1LT1 BC RW FC D DCB13DR1 3D W ACB03CR0 7D RW RDI1RO0 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RDI1RO1 BE RW CPU_SCR1 FE #	DCB12DR0	38	#	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	1
DCB12DR2 3A RW ACB02CR1 7A RW RDI1IS BA RW FA FA DCB12CR0 3B # ACB02CR2 7B RW RDI1LT0 BB RW FB FB DCB13DR0 3C # ACB03CR3 7C RW RDI1LT1 BC RW FC FC DCB13DR1 3D W ACB03CR0 7D RW RDI1RO0 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RDI1RO1 BE RW CPU_SCR1 FE #										l		1
DCB12CR0 3B # ACB02CR2 7B RW RDI1LT0 BB RW Image: RB FB FB <td></td> <td>+</td>												+
DCB13DR0 3C # ACB03CR3 7C RW RDI1LT1 BC RW FC P DCB13DR1 3D W ACB03CR0 7D RW RDI1R00 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RDI1R01 BE RW CPU_SCR1 FE #										l		
DCB13DR1 3D W ACB03CR0 7D RW RD1R00 BD RW FD FD DCB13DR2 3E RW ACB03CR1 7E RW RD1R01 BE RW CPU_SCR1 FE #												──
DCB13DR2 3E RW ACB03CR1 7E RW RDI1R01 BE RW CPU_SCR1 FE #												<u> </u>
												L
DCB13CR0 3F # ACB03CR2 7F RW BF CPU_SCR0 FF #			RW				RDI1RO1		RW			#
	DCB13CR0	3F	#	ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are reserved and should not be accessed.

Access is bit specific.



Table 5. Register Map Bank 1 Table: Configuration Space

	<u> </u>		able: Config	<u> </u>							
Name	Addr(1,Hex)	Access	Name	Addr(1,Hex)	Access	Name	Addr(1,Hex)	Access	Name	Addr(1,Hex)	Access
PRT0DM0	00	RW	DBB20FN	40	RW	ASC10CR0	80	RW	RDI2RI	C0	RW
PRT0DM1	01	RW	DBB20IN	41	RW	ASC10CR1	81	RW	RDI2SYN	C1	RW
PRT0IC0	02	RW	DBB20OU	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PRT0IC1	03	RW		43		ASC10CR3	83	RW	RDI2LT0	C3	RW
PRT1DM0	04	RW	DBB21FN	44	RW	ASD11CR0	84	RW	RDI2LT1	C4	RW
PRT1DM1	05	RW	DBB21IN	45	RW	ASD11CR1	85	RW	RDI2RO0	C5	RW
PRT1IC0	06	RW	DBB21OU	46	RW	ASD11CR2	86	RW	RDI2RO1	C6	RW
PRT1IC1	07	RW		47		ASD11CR3	87	RW		C7	-
PRT2DM0	08	RW	DCB22FN	48	RW	ASC12CR0	88	RW	RDI3RI	C8	RW
PRT2DM1	09	RW	DCB22IN	49	RW	ASC12CR1	89	RW	RDI3SYN	C9	RW
PRT2IC0	0A	RW	DCB22OU	40 4A	RW	ASC12CR2	8A	RW	RDI3IS	CA	RW
	0A 0B		DCB2200	4A 4B			8B	RW		СА	RW
PRT2IC1		RW	DODOOTU		514	ASC12CR3			RDI3LT0		
PRT3DM0	0C	RW	DCB23FN	4C	RW	ASD13CR0	8C	RW	RDI3LT1	CC	RW
PRT3DM1	0D	RW	DCB23IN	4D	RW	ASD13CR1	8D	RW	RDI3RO0	CD	RW
PRT3IC0	0E	RW	DCB23OU	4E	RW	ASD13CR2	8E	RW	RDI3RO1	CE	RW
PRT3IC1	0F	RW		4F		ASD13CR3	8F	RW		CF	
PRT4DM0	10	RW	DBB30FN	50	RW	ASD20CR0	90	RW	GDI_O_IN	D0	RW
PRT4DM1	11	RW	DBB30IN	51	RW	ASD20CR1	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW	DBB30OU	52	RW	ASD20CR2	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53	<u> </u>	ASD20CR3	93	RW	GDI_E_OU	D3	RW
PRT5DM0	14	RW	DBB31FN	54	RW	ASC21CR0	94	RW	001_2_00	D3	+
PRT5DM0 PRT5DM1			DBB31FN DBB31IN		RW	ASC21CR0 ASC21CR1		RW		D4 D5	+
	15	RW		55			95				
PRT5IC0	16	RW	DBB31OU	56	RW	ASC21CR2	96	RW		D6	
PRT5IC1	17	RW		57		ASC21CR3	97	RW		D7	
PRT6DM0	18	RW	DCB32FN	58	RW	ASD22CR0	98	RW		D8	
PRT6DM1	19	RW	DCB32IN	59	RW	ASD22CR1	99	RW		D9	
PRT6IC0	1A	RW	DCB32OU	5A	RW	ASD22CR2	9A	RW		DA	
PRT6IC1	1B	RW		5B		ASD22CR3	9B	RW		DB	-
PRT7DM0	1C	RW	DCB33FN	5C	RW	ASC23CR0	9C	RW		DC	-
PRT7DM1	1D	RW	DCB33IN	5D	RW	ASC23CR1	9D	RW	OSC_GO_EN	DD	RW
PRT7IC0	1E	RW	DCB33OU	5E	RW	ASC23CR2	9E	RW	OSC_CR4	DE	RW
PRT7IC1	1F	RW	DCD3300	5F			9F	RW		DF	RW
			0116.000		514	ASC23CR3		RW	OSC_CR3		
DBB00FN	20	RW	CLK_CR0	60	RW		A0		OSC_CR0	E0	RW
DBB00IN	21	RW	CLK_CR1	61	RW		A1		OSC_CR1	E1	RW
DBB00OU	22	RW	ABF_CR0	62	RW		A2		OSC_CR2	E2	RW
	23		AMD_CR0	63	RW		A3		VLT_CR	E3	RW
DBB01FN	24	RW		64			A4		VLT_CMP	E4	R
DBB01IN	25	RW		65			A5			E5	
DBB01OU	26	RW	AMD_CR1	66	RW		A6			E6	-
	27		ALT_CR0	67	RW		A7		DEC_CR2	E7	RW
DCB02FN	28	RW	ALT_CR1	68	RW		A8		IMO_TR	E8	W
				69	RW						W
DCB02IN	29	RW	CLK_CR2		RW		A9		ILO_TR	E9	
DCB02OU	2A	RW		6A			AA		BDG_TR	EA	RW
	2B			6B			AB		ECO_TR	EB	W
DCB03FN	2C	RW	TMP_DR0	6C	RW		AC			EC	
DCB03IN	2D	RW	TMP_DR1	6D	RW		AD	1		ED	
DCB03OU	2E	RW	TMP_DR2	6E	RW		AE			EE	Τ
	2F	1	TMP_DR3	6F	RW		AF	1		EF	1
DBB10FN	30	RW	ACB00CR3	70	RW	RDIORI	B0	RW	t	F0	1
DBB10IN	31	RW	ACB00CR0	71	RW	RDIOSYN	B1	RW		F1	+
DBB10IN DBB10OU	32	RW	ACB00CR1	72	RW	RDIOIS	B1 B2	RW		F2	+
		12.00									───
000445	33	514	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	───
DBB11FN	34	RW	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBB11IN	35	RW	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBB11OU	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
	37		ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12FN	38	RW	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	1
DCB12IN	39	RW	ACB02CR0	79	RW	RDI1SYN	B9	RW	t –	F9	1
DCB120U	3A	RW	ACB02CR1	78 7A	RW	RDI1IS	BA	RW	FLS_PR1	FA	RW
2001200	3A 3B		ACB02CR1	7B	RW	RDI1LT0	BB	RW	0	FB	+
DODIOEN		DW/									
DCB13FN	3C	RW	ACB03CR3	7C	RW	RDI1LT1	BC	RW		FC	4
DCB13IN	3D	RW	ACB03CR0	7D	RW	RDI1RO0	BD	RW		FD	<u> </u>
DCB13OU	3E	RW	ACB03CR1	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
	3F	1	ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are reserved and should not be accessed.

Access is bit specific.



Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8CLED16 EZ-Color device. For the most up-to-date electrical specifications, confirm that you have the most recent data sheet by going to the web at http://www.cypress.com.

Specifications are valid for –40 °C \leq T_A \leq 85 °C and T_J \leq 100 °C, except where noted. Refer to Table 20 for the electrical specifications for the internal main oscillator (IMO) using SLIMO mode.

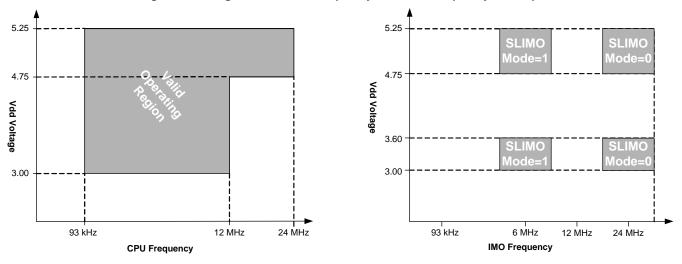


Figure 5. Voltage versus CPU Frequency, and IMO Frequency Trim Options



Absolute Maximum Ratings

Symbol	Description	Min	Тур	Max	Units	Notes
T _{STG}	Storage temperature	-55	25	+100	°C	Higher storage temperatures reduces data retention time. Recommended storage temperature is +25 °C ± 25 °C. Extended duration storage temperatures above 65 °C degrade reliability.
T _{BAKETEMP}	Bake temperature	-	125	See package label	°C	
T _{BAKETIME}	Bake time	See package label	_	72	Hours	
T _A	Ambient temperature with power applied	-40	Ι	+85	°C	
V _{DD}	Supply voltage on V _{DD} relative to Vss	-0.5	Ι	+6.0	V	
V _{IO}	DC input voltage	Vss - 0.5	-	V _{DD} + 0.5	V	
V _{IOZ}	DC Voltage applied to Tri-state	Vss - 0.5	_	V _{DD} + 0.5	V	
I _{MIO}	Maximum current into any port pin	-25	-	+50	mA	
I _{MAIO}	Maximum current into any port pin configured as analog driver	-50	_	+50	mA	
ESD	Electro static discharge voltage	2000	Ι	-	V	Human body model ESD.
LU	Latch up current	_	_	200	mA	

Operating Temperature

Symbol	Description	Min	Тур	Max	Units	Notes
T _A	Ambient temperature	-0	-	+85	°C	
TJ	Junction temperature	-0	_	+100	°C	The temperature rise from ambient to junction is package specific. See Thermal Impedances per Package on page 42. The user must limit the power consumption to comply with this requirement.



DC Electrical Characteristics

DC Chip Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40^{\circ}C \le T_A \le 85^{\circ}C$, or 3.0 V to 3.6 V and -40 °C $\le T_A \le 85^{\circ}C$, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 6. DC Chip Level Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{DD}	Supply voltage	3.00	-	5.25	V	See DC POR and LVD specifications, Table 3-15 on page 27.
I _{DD}	Supply current	-	8	14	mA	Conditions are 5.0 V, $T_A = 25$ °C, CPU = 3 MHz, SYSCLK doubler disabled, VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz.
I _{DD3}	Supply current	-	5	9	mA	Conditions are $V_{DD} = 3.3$ V, T _A = 25 °C, CPU = 3 MHz, SYSCLK doubler disabled, VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz.
I _{DDP}	Supply current when IMO = 6 MHz using SLIMO mode.	_	2	3	mA	Conditions are $V_{DD} = 3.3 \text{ V}$, $T_A = 25 \text{ °C}$, CPU = 0.75 MHz, SYSCLK doubler disabled, VC1 = 0.375 MHz, VC2 = 23.44 kHz, VC3 = 0.09 kHz.
I _{SB}	Sleep (Mode) current with POR, LVD, Sleep Timer, WDT, and internal slow oscillator active.	_	3	10	μΑ	$\begin{array}{l} \mbox{Conditions are with internal slow} \\ \mbox{speed oscillator, V}_{DD} = 3.3 \mbox{ V}, \\ -40^{\circ}C \leq T_A \leq 55 \mbox{ °C}. \end{array}$
I _{SBH}	Sleep (Mode) current with POR, LVD, Sleep Timer, WDT, and internal slow oscillator active.	_	4	25	μA	Conditions are with internal slow speed oscillator, V_{DD} = 3.3 V, 55 °C < $T_A \le 85$ °C.
I _{SBXTL}	Sleep (Mode) current with POR, LVD, Sleep Timer, WDT, internal slow oscillator, and 32 kHz crystal oscillator active.	_	4	12	μA	$ \begin{array}{l} \mbox{Conditions are with properly loaded,} \\ \mbox{1 } \mu \mbox{W max, } 32.768 \mbox{ kHz crystal.} \\ \mbox{V}_{\mbox{DD}} = 3.3 \mbox{ V}, -40 \mbox{ °C} \leq T_{\mbox{A}} \leq 55 \mbox{ °C.} \end{array} $
I _{SBXTLH}	Sleep (Mode) current with POR, LVD, sleep timer, WDT, and 32 kHz crystal oscil- lator active.	_	5	27	μA	Conditions are with properly loaded, 1 μ W max, 32.768 kHz crystal. V _{DD} = 3.3 V, 55 °C < T _A ≤ 85 °C.
V _{REF}	Reference voltage (Bandgap)	1.28	1.3	1.32	V	Trimmed for appropriate V _{DD} .



DC GPIO Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 7. DC GPIO Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
R _{PU}	Pull-up Resistor	4	5.6	8	kΩ	
R _{PD}	Pull-down Resistor	4	5.6	8	kΩ	
V _{OH}	High output level	V _{DD} - 1.0	-	-	V	IOH = 10 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 80 mA maximum combined IOH budget.
V _{OL}	Low output level	_	_	0.75	V	IOL = 25 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 150 mA maximum combined IOL budget.
I _{OH}	High level source current	10	-	-	mA	VOH = V_{DD} -1.0 V. See the limitations of the total current in the Note for VOH.
I _{OL}	Low level sink current	25	-	-	mA	VOL = 0.75 V. See the limitations of the total current in the Note for VOL.
V _{IL}	Input low level	_	-	0.8	V	V _{DD} = 3.0 to 5.25.
V _{IH}	Input high level	2.1	-		V	V _{DD} = 3.0 to 5.25.
V _H	Input hysterisis	_	60	_	mV	
IIL	Input leakage (Absolute Value)	-	1	—	nA	Gross tested to 1 µA.
C _{IN}	Capacitive load on pins as input	-	3.5	10	pF	Package and pin dependent. Temp = 25 °C.
C _{OUT}	Capacitive load on pins as output	_	3.5	10	pF	Package and pin dependent. Temp =25 °C.



DC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40 \degree C \le T_A \le 85 \degree C$, or 3.0 V to 3.6 V and $-40 \degree C \le T_A \le 85 \degree C$, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

The operational amplifier is a component of both the Analog Continuous Time PSoC blocks and the analog switched capacitor PSoC blocks. The guaranteed specifications are measured in the Analog Continuous Time PSoC block. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Symbol	Description	Min	Тур	Max	Unit	Notes
V _{OSOA}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low	_	1.6	10	mV	_
	Power = Low, Opamp bias = High	-	1.6	10	mV	
	Power = Medium, Opamp bias = Low	-	1.6	10	mV	
	Power = Medium, Opamp bias = High	-	1.6	10	mV	
	Power = High, Opamp bias = Low Power = High, Opamp bias = High	_	1.6 1.6	10 10	mV mV	
TCV _{OSOA}	Average input offset voltage drift	_	4	23	μV/°C	
1	Input leakage current (port 0 analog pins)	_	200	-	pA	Gross tested to 1 µA
'EBOA		_				•
C _{INOA}	Input capacitance (port 0 analog pins)	_	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
CMOA	Common mode voltage range (All cases, except Power = High, Opamp bias = High)	0	_	V _{DD}	V	The common-mode input voltage range is measured through an analog output buffer.
	Common mode voltage range (Power = High, Opamp bias = High)	0.5	_	V _{DD} – 0.5	V	The specification includes the limitations imposed by the characteristics of the analog output buffer.
CMRROA	Common mode rejection ratio	60	-	-	dB	-
GOLOA	Open loop gain	80	-	-	dB	-
V _{OHIGHOA}	High output voltage swing (internal signals)	V _{DD} - 0.01	_	-	V	-
V _{OLOWOA}	Low output voltage swing (internal signals)	-	-	0.1	V	-
I _{SOA}	Supply current (including associated AGND buffer)					-
	Power = Low, Opamp bias = Low	-	150	200	μA	
	Power = Low, Opamp bias = High	-	300	400	μA	
	Power = Medium, Opamp bias = Low	-	600	800	μA	
	Power = Medium, Opamp bias = High	-	1200	1600	μA	
	Power = High, Opamp bias = Low	-	2400	3200	μA	
	Power = High, Opamp bias = High	-	4600	6400	μA	
PSRR _{OA}	Supply voltage rejection ratio	67	80	-	dB	$ \begin{aligned} & V_{SS} \leq V_{IN} \leq (V_{DD} - 2.25) \text{ or} \\ & (V_{DD} - 1.25 \text{ V}) \leq V_{IN} \leq V_{DD}. \end{aligned} $

Table 8. 5-V DC Operational Amplifier Specifications



Table 9. 3.3-V DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Unit	Notes
V _{OSOA}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	- - - - -	1.4 1.4 1.4 1.4 1.4 1.4	10 10 10 10 10 -	mV mV mV mV mV	Power = High, Opamp bias = High setting is not allowed for 3.3 V V _{DD} operation.
TCV _{OSOA}	Average input offset voltage drift	-	7	40	µV/°C	-
EBOA	Input leakage current (port 0 analog pins)	-	200	-	pА	Gross tested to 1 µA.
C _{INOA}	Input capacitance (port 0 analog pins)	-	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
СМОА	Common mode voltage range	0	_	V _{DD}	V	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
CMRR _{OA}	Common mode rejection ratio	60	-	-	dB	-
G _{OLOA}	Open loop gain	80	-	-	dB	-
V _{OHIGHOA}	High output voltage swing (internal signals)	V _{DD} – 0.01	-	-	V	-
V _{OLOWOA}	Low output voltage swing (internal signals)	-	-	0.01	V	-
I _{SOA}	Supply current (including associated AGND buffer) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	- - - - -	150 300 600 1200 2400 -	200 400 800 1600 3200 -	μΑ μΑ μΑ μΑ μΑ	Power = High, Opamp bias = High setting is not allowed for 3.3 V V _{DD} operation.
PSRR _{OA}	Supply voltage rejection ratio	54	80	_	dB	$V_{SS} \leq V_{IN} \leq (V_{DD} - 2.25) \text{ or} \\ (V_{DD} - 1.25 \text{ V}) \leq V_{IN} \leq V_{DD}$

DC Low Power Comparator Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 10. DC Low Power Comparator Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{REFLPC}	Low power comparator (LPC) reference voltage range	0.2	-	V _{DD} - 1	V	_
I _{SLPC}	LPC supply current	-	10	40	μΑ	-
V _{OSLPC}	LPC voltage offset	-	2.5	30	mV	-



DC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 11. 5-V DC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Max	Unit	Notes
V _{OSOB}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	- - - -	3.2 3.2 3.2 3.2 3.2	18 18 18 18	mV mV mV mV	_
TCV _{OSOB}	Average input offset voltage drift	-	5.5	26	µV/°C	-
V _{CMOB}	Common-mode input voltage range	0.5	-	V _{DD} – 1.0	V	-
R _{OUTOB}	Output resistance Power = Low Power = High		-	1 1	$\Omega \Omega$	_
V _{OHIGHOB}	High output voltage swing (Load = 32 ohms to V _{DD} /2) Power = Low Power = High	0.5 × V _{DD} + 1.3 0.5 × V _{DD} + 1.3			V V	-
V _{OLOWOB}	Low output voltage swing (Load = 32 ohms to V _{DD} /2) Power = Low Power = High			0.5 × V _{DD} – 1.3 0.5 × V _{DD} – 1.3	V V	-
I _{SOB}	Supply current including bias cell (no load) Power = Low Power = High		1.1 2.6	2 5	mA mA	-
PSRR _{OB}	Supply voltage rejection ratio	40	64		dB	-
CL	Load capacitance	-	-	200	pF	This specification applies to the external circuit driven by the analog output buffer.

Table 12. 3.3-V DC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Мах	Unit	Notes
V _{OSOB}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	- - - -	3.2 3.2 6 6	20 20 25 25	mV mV mV mV	High power setting is not recommended.
TCV _{OSOB}	Average input offset voltage drift Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	- - - -	8 8 12 12	32 32 41 41	μV/°C μV/°C μV/°C μV/°C	High power setting is not recommended.
V _{CMOB}	Common-mode input voltage range	0.5	-	V _{DD} – 1.0	V	-
R _{OUTOB}	Output resistance Power = Low Power = High			10 10	W W	_
V _{OHIGHOB}	High output voltage swing (Load = 32 ohms to V _{DD} /2) Power = Low Power = High	0.5 × V _{DD} + 1.0 0.5 × V _{DD} + 1.0		-	V V	-
V _{OLOWOB}	Low output voltage swing (Load = 32 ohms to V _{DD} /2) Power = Low Power = High			0.5 × V _{DD} – 1.0 0.5 × V _{DD} – 1.0	V V	-



Table 12. 3.3-V DC Analog Output Buffer Specifications (continued)

Symbol	Description	Min	Тур	Мах	Unit	Notes
I _{SOB}	Supply current including bias cell (no load) Power = Low Power = High		0.8 2.0	1 5	mA mA	-
PSRR _{OB}	Supply voltage rejection ratio	60	64	_	dB	
CL	Load capacitance	-	_	200	pF	This specification applies to the external circuit driven by the analog output buffer.

DC Switch Mode Pump Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

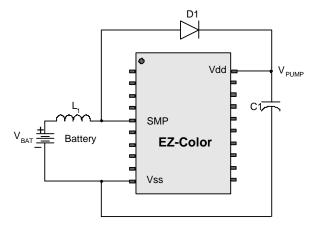
Table 13. DC Switch Mode Pump (SMP) Specifications

Symbol	Description	Min	Тур	Мах	Units	Notes
V _{PUMP} 5V	5 V output voltage at V _{DD} from Pump	4.75	5.0	5.25	V	Configured as in Note 3. Average, neglecting ripple. SMP trip voltage is set to 5.0 V.
V _{PUMP} 3V	3 V output voltage at V_{DD} from Pump	3.00	3.25	3.60	V	Configured as in Note 3. Average, neglecting ripple. SMP trip voltage is set to 3.25 V.
I _{PUMP}	Available output current V _{BAT} = 1.5 V, V _{PUMP} = 3.25 V V _{BAT} = 1.8 V, V _{PUMP} = 5.0 V	8 5			mA mA	Configured as in Note 3. SMP trip voltage is set to 3.25 V. SMP trip voltage is set to 5.0 V.
V _{BAT} 5V	Input voltage range from battery	1.8	-	5.0	V	Configured as in Note 3. SMP trip voltage is set to 5.0 V.
V _{BAT} 3V	Input voltage range from battery	1.0	3–	3.3	V	Configured as in Note 3 SMP trip voltage is set to 3.25 V.
VBATSTART	Minimum input voltage from battery to start Pump	1.2	-	-	V	Configured as in Note 3. 0 °C \leq T _A \leq 100. 1.25 V at T _A = -40 °C.
ΔV_{PUMP}_{Line}	Line regulation (over V _{BAT} range)	_	5	_	%V _O	Configured as in Note 3. V _O is the "V _{DD} Value for PUMP Trip" specified by the VM[2:0] setting in Table 17, "DC POR, SMP, and LVD Specifications," on page 28.
ΔV_{PUMP_Load}	Load regulation	_	5	_	%V _O	Configured as in Note 3. V _O is the "V _{DD} Value for PUMP Trip" specified by the VM[2:0] setting in Table 17, "DC POR, SMP, and LVD Specifications," on page 28.
ΔV_{PUMP_Rippl} e	Output Voltage Ripple (depends on capacitor/load)	-	100	-	mVpp	Configured as in Note 3. Load is 5 mA.
E ₃	Efficiency	35	50	_	%	Configured as in Note 3. Load is 5 mA. SMP trip voltage is set to 3.25 V.
F _{PUMP}	Switching Frequency	Ι	1.4	_	MHz	-
DC _{PUMP}	Switching Duty Cycle	_	50	_	%	-

Note 3. $L_1 = 2 \text{ mH}$ inductor, $C_1 = 10 \text{ mF}$ capacitor, $D_1 = \text{Schottky diode}$. See Figure 6.



Figure 6. Basic Switch Mode Pump Circuit



DC Analog Reference Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

The guaranteed specifications are measured through the analog continuous time PSoC blocks. The power levels for AGND refer to the power of the Analog Continuous Time PSoC block. The power levels for RefHi and RefLo refer to the analog reference control register. The limits stated for AGND include the offset error of the AGND buffer local to the Analog Continuous Time PSoC block. Reference control power is high.

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Unit
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.228	V _{DD} /2 + 1.290	$V_{DD}/2 + 1.352$	V
		V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.078$	$V_{DD}/2 - 0.007$	$V_{DD}/2 + 0.063$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.336	V _{DD} /2 – 1.295	V _{DD} /2 - 1.250	V
	RefPower = High	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.224	V _{DD} /2 + 1.293	$V_{DD}/2 + 1.356$	V
	Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.056$	V _{DD} /2 - 0.005	$V_{DD}/2 + 0.043$	V
0b000		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.338	V _{DD} /2 – 1.298	V _{DD} /2 - 1.255	V
00000	RefPower = Med	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.226	V _{DD} /2 + 1.293	$V_{DD}/2 + 1.356$	V
	Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.057$	V _{DD} /2-0.006	$V_{DD}/2 + 0.044$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.337	V _{DD} /2 – 1.298	V _{DD} /2 - 1.256	V
	RefPower = Med Opamp bias = Low	V _{REFHI}	Ref High	V _{DD} /2 + Bandgap	V _{DD} /2 + 1.226	V _{DD} /2 + 1.294	$V_{DD}/2 + 1.359$	V
		V _{AGND}	AGND	V _{DD} /2	$V_{DD}/2 - 0.047$	V _{DD} /2 - 0.004	$V_{DD}/2 + 0.035$	V
		V _{REFLO}	Ref Low	V _{DD} /2 – Bandgap	V _{DD} /2 – 1.338	V _{DD} /2 – 1.299	V _{DD} /2 – 1.258	V

Table 14. 5-V DC Analog Reference Specifications



Table 14. 5-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Unit
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] + P2[6] - 0.085	P2[4] + P2[6] - 0.016	P2[4] + P2[6] + 0.044	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	$\begin{array}{l} P2[4] - P2[6] \\ (P2[4] = V_{DD}/2, \\ P2[6] = 1.3 \ V) \end{array}$	P2[4] – P2[6] – 0.022	P2[4] – P2[6] + 0.010	P2[4]-P2[6]+ 0.055	V
	RefPower = High Opamp bias = Low	V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] + P2[6] - 0.077	P2[4] + P2[6] - 0.010	P2[4] + P2[6] + 0.051	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
01-004		V _{REFLO}	Ref Low	P2[4] – P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] – P2[6] – 0.022	P2[4] – P2[6] + 0.005	P2[4]-P2[6]+ 0.039	V
0b001	RefPower = Med Opamp bias = High	V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] + P2[6] - 0.070	P2[4] + P2[6] - 0.010	P2[4] + P2[6] + 0.050	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] – P2[6] – 0.022	P2[4] – P2[6] + 0.005	P2[4]-P2[6]+ 0.039	V
	RefPower = Med Opamp bias = Low	V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] + P2[6] - 0.070	P2[4] + P2[6] - 0.007	P2[4] + P2[6] + 0.054	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] - P2[6] (P2[4] = V _{DD} /2, P2[6] = 1.3 V)	P2[4] – P2[6] – 0.022	P2[4] – P2[6] + 0.002	P2[4]-P2[6]+ 0.032	V
	RefPower = High	V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.037	V _{DD} – 0.009	V _{DD}	V
	Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2-0.061	V _{DD} /2 – 0.006	$V_{DD}/2 + 0.047$	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.007	V _{SS} + 0.028	V
	RefPower = High	V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.039	V _{DD} – 0.006	V _{DD}	V
	Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2-0.049	V _{DD} /2 – 0.005	$V_{DD}/2 + 0.036$	V
05040		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.005	V _{SS} + 0.019	V
0b010	RefPower = Med	V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.037	V _{DD} – 0.007	V _{DD}	V
	Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2-0.054	V _{DD} /2 - 0.005	V _{DD} /2 + 0.041	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.024	V
	RefPower = Med	V _{REFHI}	Ref High	V _{DD}	V _{DD} - 0.042	V _{DD} – 0.005	V _{DD}	V
	Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.046	V _{DD} /2 - 0.004	$V_{DD}/2 + 0.034$	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.004	V _{SS} + 0.017	V



Table 14. 5-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Unit
	RefPower = High	V _{REFHI}	Ref High	3 × Bandgap	3.788	3.891	3.986	V
	Opamp bias = High	V _{AGND}	AGND	2 × Bandgap	2.500	2.604	3.699	V
		V _{REFLO}	Ref Low	Bandgap	1.257	1.306	1.359	V
	RefPower = High	V _{REFHI}	Ref High	3 × Bandgap	3.792	3.893	3.982	V
	Opamp bias = Low	V _{AGND}	AGND	2 × Bandgap	2.518	2.602	2.692	V
0b011		V _{REFLO}	Ref Low	Bandgap	1.256	1.302	1.354	V
00011	RefPower = Med	V _{REFHI}	Ref High	3 × Bandgap	3.795	3.894	3.993	V
	Opamp bias = High	V _{AGND}	AGND	2 × Bandgap	2.516	2.603	2.698	V
		V _{REFLO}	Ref Low	Bandgap	1.256	1.303	1.353	V
	RefPower = Med	V _{REFHI}	Ref High	3 × Bandgap	3.792	3.895	3.986	V
	Opamp bias = Low	V _{AGND}	AGND	2 × Bandgap	2.522	2.602	2.685	V
		V _{REFLO}	Ref Low	Bandgap	1.255	1.301	1.350	V
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.495 – P2[6]	2.586 – P2[6]	2.657 – P2[6]	V
		V _{AGND}	AGND	2 × Bandgap	2.502	2.604	2.719	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.531 – P2[6]	2.611 – P2[6]	2.681 – P2[6]	V
	RefPower = High Opamp bias = Low	V _{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.500 – P2[6]	2.591 – P2[6]	2.662 – P2[6]	V
		V _{AGND}	AGND	2 × Bandgap	2.519	2.602	2.693	V
05400		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.530 – P2[6]	2.605 – P2[6]	2.666 – P2[6]	V
0b100	RefPower = Med Opamp bias = High	V _{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.503 – P2[6]	2.592 – P2[6]	2.662 – P2[6]	V
		V _{AGND}	AGND	2 × Bandgap	2.517	2.603	2.698	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.529 – P2[6]	2.606 – P2[6]	2.665 – P2[6]	V
	RefPower = Med Opamp bias = Low	V _{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.505 – P2[6]	2.594 – P2[6]	2.665 – P2[6]	V
		V _{AGND}	AGND	2 × Bandgap	2.525	2.602	2.685	V
		V _{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.528 – P2[6]	2.603 – P2[6]	2.661 – P2[6]	V



Table 14. 5-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Мах	Unit
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.222	P2[4] + 1.290	P2[4] + 1.343	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.331	P2[4] – 1.295	P2[4] – 1.254	V
	RefPower = High Opamp bias = Low	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.226	P2[4] + 1.293	P2[4] + 1.347	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
05404		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.331	P2[4] – 1.298	P2[4] – 1.259	V
0b101	RefPower = Med Opamp bias = High	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.227	P2[4] + 1.294	P2[4] + 1.347	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.331	P2[4] – 1.298	P2[4] – 1.259	V
	RefPower = Med Opamp bias = Low	V _{REFHI}	Ref High	P2[4] + Bandgap (P2[4] = V _{DD} /2)	P2[4] + 1.228	P2[4] + 1.295	P2[4] + 1.349	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – Bandgap (P2[4] = V _{DD} /2)	P2[4] – 1.332	P2[4] – 1.299	P2[4] – 1.260	V
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	2 × Bandgap	2.535	2.598	2.644	V
		V _{AGND}	AGND	Bandgap	1.227	1.305	1.398	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.009	V _{SS} + 0.038	V
	RefPower = High Opamp bias = Low	V _{REFHI}	Ref High	2 × Bandgap	2.530	2.598	2.643	V
		V _{AGND}	AGND	Bandgap	1.244	1.303	1.370	V
0b110		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.005	V _{SS} + 0.024	V
01100	RefPower = Med	V _{REFHI}	Ref High	2 × Bandgap	2.532	2.598	2.644	V
	Opamp bias = High	V _{AGND}	AGND	Bandgap	1.239	1.304	1.380	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.026	V
	RefPower = Med	V _{REFHI}	Ref High	2 × Bandgap	2.528	2.598	2.645	V
	Opamp bias = Low	V _{AGND}	AGND	Bandgap	1.249	1.302	1.362	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.004	V _{SS} + 0.018	V
	RefPower = High	V _{REFHI}	Ref High	3.2 × Bandgap	4.041	4.155	4.234	V
	Opamp bias = High	V _{AGND}	AGND	1.6 × Bandgap	1.998	2.083	2.183	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.010	V _{SS} + 0.038	V
	RefPower = High	V _{REFHI}	Ref High	3.2 × Bandgap	4.047	4.153	4.236	V
	Opamp bias = Low	V _{AGND}	AGND	1.6 × Bandgap	2.012	2.082	2.157	V
0b111		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.024	V
	RefPower = Med	V _{REFHI}	Ref High	3.2 × Bandgap	4.049	4.154	4.238	V
	Opamp bias = High	V _{AGND}	AGND	1.6 × Bandgap	2.008	2.083	2.165	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.006	V _{SS} + 0.026	V
	RefPower = Med	V _{REFHI}	Ref High	3.2 × Bandgap	4.047	4.154	4.238	V
	Opamp bias = Low	V _{AGND}	AGND	1.6 × Bandgap	2.016	2.081	2.150	V
		V _{REFLO}	Ref Low	V _{SS}	V _{SS}	V _{SS} + 0.004	V _{SS} + 0.018	V



Table 15. 3.3-V DC Analog Reference Specifications

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Мах	Unit
		V _{REFHI}	Ref High	V _{DD} /2 + BandGap	V _{DD} /2 + 1.225	V _{DD} /2 + 1.292	V _{DD} /2 + 1.361	V
	RefPower = High Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.067	V _{DD} /2 - 0.002	$V_{DD}/2 + 0.063$	V
	Jan	V _{REFLO}	Ref Low	V _{DD} /2 – BandGap	V _{DD} /2 – 1.35	V _{DD} /2 - 1.293	V _{DD} /2 - 1.210	V
		V _{REFHI}	Ref High	V _{DD} /2 + BandGap	V _{DD} /2 + 1.218	V _{DD} /2 + 1.294	V _{DD} /2 + 1.370	V
	RefPower = High Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.038	V _{DD} /2 - 0.001	V _{DD} /2 + 0.035	V
01-000		V _{REFLO}	Ref Low	V _{DD} /2 – BandGap	V _{DD} /2 - 1.329	V _{DD} /2 - 1.296	V _{DD} /2 - 1.259	V
0b000		V _{REFHI}	Ref High	V _{DD} /2 + BandGap	V _{DD} /2 + 1.221	V _{DD} /2 + 1.294	V _{DD} /2 + 1.366	V
	RefPower = Med Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.050	V _{DD} /2 - 0.002	V _{DD} /2 + 0.046	V
	- participation - might	V _{REFLO}	Ref Low	V _{DD} /2 – BandGap	V _{DD} /2 – 1.331	V _{DD} /2 – 1.296	V _{DD} /2 - 1.260	V
		V _{REFHI}	Ref High	V _{DD} /2 + BandGap	V _{DD} /2 + 1.226	V _{DD} /2 + 1.295	V _{DD} /2 + 1.365	V
	RefPower = Med Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.028	V _{DD} /2 - 0.001	V _{DD} /2 + 0.025	V
	- Family 2000 - 200	V _{REFLO}	Ref Low	V _{DD} /2 – BandGap	V _{DD} /2 - 1.329	V _{DD} /2 – 1.297	V _{DD} /2 – 1.262	V
		V _{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.098	P2[4] + P2[6] - 0.018	P2[4] + P2[6] + 0.055	V
	RefPower = High Opamp bias = High	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
		V _{REFLO}	Ref Low	P2[4] – P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.055	P2[4] – P2[6] + 0.013	P2[4] – P2[6] + 0.086	V
		V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.082	P2[4] + P2[6] - 0.011	P2[4] + P2[6] + 0.050	V
	RefPower = High Opamp bias = Low	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
0b001		V _{REFLO}	Ref Low	P2[4] – P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.037	P2[4] – P2[6] + 0.006	P2[4] – P2[6] + 0.054	V
05001		V _{REFHI}	Ref High	P2[4] + P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.079	P2[4] + P2[6] - 0.012	P2[4] + P2[6] + 0.047	V
	RefPower = Med Opamp bias = High	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	_
		V _{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.038	P2[4] – P2[6] + 0.006	P2[4] – P2[6] + 0.057	V
		V _{REFHI}	Ref High	P2[4]+P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] + P2[6] - 0.080	P2[4] + P2[6] - 0.008	P2[4] + P2[6] + 0.055	V
	RefPower = Med Opamp bias = Low	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	-
	Opamp bias = Low	V _{REFLO}	Ref Low	P2[4]–P2[6] (P2[4] = V _{DD} /2, P2[6] = 0.5 V)	P2[4] – P2[6] – 0.032	P2[4] – P2[6] + 0.003	P2[4] – P2[6] + 0.042	V



Table 15. 3.3-V DC Analog Reference Specificat	ions (continued)
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Reference ARF_CR[5:3]	eference F_CR[5:3]Reference Power SettingsSymbolReferenceDescription		Min	Тур	Мах	Unit		
		V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.06	V _{DD} – 0.010	V _{DD}	V
	RefPower = High Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.05	V _{DD} /2 - 0.002	V _{DD} /2 + 0.040	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.009	Vss + 0.056	V
06010		V _{REFHI}	Ref High	V _{DD}	V _{DD} - 0.060	V _{DD} – 0.006	V _{DD}	V
	RefPower = High Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.028	V _{DD} /2 – 0.001	V _{DD} /2 + 0.025	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.005	Vss + 0.034	V
01000		V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.058	V _{DD} – 0.008	V _{DD}	V
	RefPower = Med Opamp bias = High	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.037	V _{DD} /2 - 0.002	V _{DD} /2 + 0.033	V
	5101100	V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.007	Vss + 0.046	V
		V _{REFHI}	Ref High	V _{DD}	V _{DD} – 0.057	V _{DD} – 0.006	V _{DD}	V
	RefPower = Med Opamp bias = Low	V _{AGND}	AGND	V _{DD} /2	V _{DD} /2 - 0.025	V _{DD} /2 – 0.001	V _{DD} /2 + 0.022	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.004	Vss + 0.030	V
0b011	All power settings. Not allowed for 3.3 V	_	-	_	-	_	_	-
0b100	All power settings. Not allowed for 3.3 V	-	-	_	-	_	_	-
	RefPower = High Opamp bias = High	V _{REFHI}	Ref High	P2[4] + BandGap (P2[4] = V _{DD} /2)	P2[4] + 1.213	P2[4] + 1.291	P2[4] + 1.367	V
		V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V _{REFLO}	Ref Low	P2[4] – BandGap (P2[4] = V _{DD} /2)	P2[4] – 1.333	P2[4] – 1.294	P2[4] – 1.208	V
		V _{REFHI}	Ref High	P2[4] + BandGap (P2[4] = V _{DD} /2)	P2[4] + 1.217	P2[4] + 1.294	P2[4] + 1.368	V
	RefPower = High Opamp bias = Low	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
0b101		V _{REFLO}	Ref Low	P2[4] – BandGap (P2[4] = V _{DD} /2)	P2[4] – 1.320	P2[4] – 1.296	P2[4] – 1.261	V
10100		V _{REFHI}	Ref High	P2[4] + BandGap (P2[4] = V _{DD} /2)	P2[4] + 1.217	P2[4] + 1.294	P2[4] + 1.369	V
	RefPower = Med Opamp bias = High	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V _{REFLO}	Ref Low	P2[4] – BandGap (P2[4] = V _{DD} /2)	P2[4] – 1.322	P2[4] – 1.297	P2[4] – 1.262	V
		V _{REFHI}	Ref High	P2[4] + BandGap (P2[4] = V _{DD} /2)	P2[4] + 1.219	P2[4] + 1.295	P2[4] + 1.37	V
	RefPower = Med Opamp bias = Low	V _{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V _{REFLO}	Ref Low	P2[4] – BandGap (P2[4] = V _{DD} /2)	P2[4] – 1.324	P2[4] – 1.297	P2[4] – 1.262	V



Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Тур	Max	Unit
		V _{REFHI}	Ref High	Ref High 2 × BandGap		2.598	2.698	V
	RefPower = High Opamp bias = High		AGND	BandGap	1.203	1.307	1.424	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.012	Vss + 0.067	V
		V _{REFHI}	Ref High	2 × BandGap	2.516	2.598	2.683	V
	RefPower = High Opamp bias = Low	V _{AGND}	AGND	BandGap	1.241	1.303	1.376	V
0b110		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.007	Vss + 0.040	V
00110	RefPower = Med Opamp bias = High	V _{REFHI}	Ref High	2 × BandGap	2.510	2.599	2.693	V
		V _{AGND}	AGND	BandGap	1.240	1.305	1.374	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.008	Vss + 0.048	V
		V _{REFHI}	Ref High	2 × BandGap	2.515	2.598	2.683	V
	RefPower = Med Opamp bias = Low	V _{AGND}	AGND	BandGap	1.258	1.302	1.355	V
		V _{REFLO}	Ref Low	Vss	Vss	Vss + 0.005	Vss + 0.03	V
0b111	All power settings. Not allowed for 3.3 V.	-	-	_	-	_	_	_

Table 15. 3.3-V DC Analog Reference Specifications (continued)

DC Analog PSoC Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 16. DC Analog PSoC Block Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
R _{CT}	Resistor Unit Value (Continuous Time)	-	12.2	-	kΩ	
C _{SC}	Capacitor Unit Value (Switched Capacitor)	-	80	-	fF	

DC POR, SMP, and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and $-40 \degree C \le T_A \le 85 \degree C$, or 3.0 V to 3.6 V and $-40 \degree C \le T_A \le 85 \degree C$, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 17. DC POR, SMP, and LVD	Specifications
--------------------------------	----------------

Symbol	Description	Min	Тур	Max	Units	Notes
V _{PPOR0R} V _{PPOR1R} V _{PPOR2R}	PORLEV[1:0] = 01b	_	2.91 4.39 4.55	-	>>>	
V _{PPOR0} V _{PPOR1} V _{PPOR2}	V _{DD} Value for PPOR Trip (negative ramp) PORLEV[1:0] = 00b PORLEV[1:0] = 01b PORLEV[1:0] = 10b	_	2.82 4.39 4.55	_	V V V	
V _{PH0} V _{PH1} V _{PH2}	PPOR Hysteresis PORLEV[1:0] = 00b PORLEV[1:0] = 01b PORLEV[1:0] = 10b	_ _ _	92 0 0		mV mV mV	

Notes

4. Always greater than 50 mV above PPOR (PORLEV = 00) for falling supply.

5. Always greater than 50 mV above PPOR (PORLEV = 10) for falling supply.



Table 17.	DC POR,	SMP,	and LVD	Specifications	(con	tinued)	

Symbol	Description	Min	Тур	Max	Units	Notes
	V _{DD} Value for LVD Trip					
V _{LVD0}	VM[2:0] = 000b	2.86	2.92	2.98 ^[4]	V	
V _{LVD1}	VM[2:0] = 001b	2.96	3.02	3.08	V	
V _{LVD2}	VM[2:0] = 010b	3.07	3.13	3.20	V	
V _{LVD3}	VM[2:0] = 011b	3.92	4.00	4.08	V	
V _{LVD4}	VM[2:0] = 100b	4.39	4.48	4.57	V	
V _{LVD5}	VM[2:0] = 101b	4.55	4.64	4.74 ^[5]	V	
V _{LVD6}	VM[2:0] = 110b	4.63	4.73	4.82	V	
V _{LVD7}	VM[2:0] = 111b	4.72	4.81	4.91	V	
					V	
	V _{DD} Value for SMP Trip					
V _{PUMP0}	VM[2:0] = 000b	2.96	3.02	3.08	V	
V _{PUMP1}	VM[2:0] = 001b	3.03	3.10	3.16	V	
V _{PUMP2}	VM[2:0] = 010b	3.18	3.25	3.32	V	
V _{PUMP3}	VM[2:0] = 011b	4.11	4.19	4.28	V	
V _{PUMP4}	VM[2:0] = 100b	4.55	4.64	4.74	V	
V _{PUMP5}	VM[2:0] = 101b	4.63	4.73	4.82	V	
V _{PUMP6}	VM[2:0] = 110b	4.72	4.82	4.91	V	
V _{PUMP7}	VM[2:0] = 111b	4.90	5.00	5.10	V	
					V	



DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and --40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 18. DC Programming Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{DDP}	V _{DD} for programming and erase	4.5	5	5.5	V	This specification applies to the functional requirements of external programmer tools.
V _{DDLV}	Low V _{DD} for verify	3.0	3.1	3.2	V	This specification applies to the functional requirements of external programmer tools.
V _{DDHV}	High V _{DD} for verify	5.1	5.2	5.3	V	This specification applies to the functional requirements of external programmer tools.
V _{DDIWRITE}	Supply voltage for flash write operation	3.15	-	5.25	V	This specification applies to this device when it is executing internal flash writes.
I _{DDP}	Supply current during programming or verify	-	10	30	mA	
V _{ILP}	Input Low-voltage during programming or verify	-	-	0.8	V	
V _{IHP}	Input High-voltage during programming or verify	2.2	-	-	V	
I _{ILP}	Input Current when Applying V _{ILP} to P1[0] or P1[1] During Programming or Verify	-	-	0.2	mA	Driving internal pull-down resistor.
I _{IHP}	Input Current when Applying V _{IHP} to P1[0] or P1[1] During Programming or Verify	-	-	1.5	mA	Driving internal pull-down resistor.
V _{OLV}	Output Low-voltage during programming or verify	-	-	Vss + 0.75	V	
V _{OHV}	Output High-voltage during programming or verify	V _{DD} - 1.0	-	V _{DD}	V	
Flash _{ENPB}	flash endurance (per block)	50,000 ^[6]	-	-	-	Erase/write cycles per block.
Flash _{ENT}	flash endurance (total) ^[7]	1,800,000	_	-	-	Erase/write cycles.
Flash _{DR}	flash data retention	10	-	-	Years	

DC I²C Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 19. DC I²C Specifications

Parameter	Description	Min	Тур	Max	Units	Notes
V _{ILI2C} ^[8]	Input low level	-	-	0.3 × V _{DD}	V	$3.0~V \leq V_{DD} \leq 3.6~V$
		-	-	0.25 × V _{DD}	V	$4.75~V \leq V_{DD} \leq 5.25~V$
V _{IHI2C} ^[8]	Input high level	$0.7 \times V_{DD}$	-	-	V	$3.0~V \leq V_{DD} \leq 5.25~V$

Notes

- 6. The 50,000 cycle flash endurance per block is only guaranteed if the Flash is operating within one voltage range. Voltage ranges are 3.0 V to 3.6 V and 4.75 V to 5.25 V.
- 4.75 V to 5.25 V.
 7. A maximum of 36 x 50,000 block endurance cycles is allowed. This may be balanced between operations on 36x1 blocks of 50,000 maximum cycles each, 36x2 blocks of 25,000 maximum cycles each, or 36x4 blocks of 12,500 maximum cycles each (to limit the total number of cycles to 36x50,000 and that no single block ever sees more than 50,000 cycles). For the full industrial range, the user must employ a temperature sensor user module (flashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at http://www.cypress.com under Application Notes for more information.
 8. All GPIOs meet the DC GPIO V_{IL} and V_{IH} specifications found in the DC GPIO specifications sections. The I²C GPIO pins also meet the mentioned specs.



AC Electrical Characteristics

AC Chip Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Note See the individual user module data sheets for information on maximum frequencies for user modules.

Symbol	Description	Min	Тур	Max	Units	Notes
F _{IMO24}	Internal main oscillator frequency for 24 MHz	23.4	24	24.6 ^[9,10,11]	MHz	Trimmed for 5 V or 3.3 V operation using factory trim values. See the figure on page 19. SLIMO Mode = 0.
F _{IMO6}	Internal main oscillator frequency for 6 MHz	5.5	6	6.5 ^[9,10,11]	MHz	Trimmed for 5 V or 3.3 V operation using factory trim values. See the figure on page 19. SLIMO Mode = 1.
F _{CPU1}	CPU frequency (5 V Nominal)	0.0914	24	24.6 ^[9,10]	MHz	-
F _{CPU2}	CPU frequency (3.3 V Nominal)	0.0914	12	12.3 ^[10,11]	MHz	-
F _{48M}	Digital PSoC block frequency	0	48	49.2 ^[9,10,12]	MHz	Refer to the AC Digital Block Speci- fications below.
F _{24M}	Digital PSoC block frequency	0	24	24.6 ^[10,12]	MHz	-
F _{32K1}	Internal low speed oscillator frequency	15	32	64	kHz	-
F _{32K_U}	Internal low speed oscillator untrimmed frequency	5	_	100	kHz	After a reset and before the M8C starts to run, the ILO is not trimmed. See the System Resets section of the <i>PSoC Technical</i> <i>Reference Manual</i> for details on timing this.
DC _{ILO}	Internal low speed oscillator duty cycle	20	50	80	%	-
F _{32K2}	External crystal oscillator	-	32.768	-	kHz	Accuracy is capacitor and crystal dependent. 50% duty cycle.
F _{PLL}	PLL frequency	-	23.986	-	MHz	A multiple (x732) of crystal frequency.
T _{PLLSLEW}	PLL lock time	0.5	_	10	ms	-
T _{PLLSLEWL} OW	PLL lock time for low gain setting	0.5	-	50	ms	-
T _{OS}	External crystal oscillator startup to 1%	_	250	500	ms	-
T _{OSACC}	External crystal oscillator startup to 100 ppm	-	300	600	ms	The crystal oscillator frequency is within 100 ppm of its final value by the end of the T_{osacc} period. Correct operation assumes a properly loaded 1 μ W maximum drive level 32.768 kHz crystal. 3.0V $\leq V_{DD} \leq 5.5$ V, -40 °C $\leq T_A \leq 85$ °C.
T _{XRST}	External reset pulse width	10	_	_	μS	_
DC24M	24 MHz duty cycle	40	50	60	%	_
Step24M	24 MHz trim step size	_	50	_	kHz	_

Notes

 Notes

 9. 4.75 V < V_{DD} < 5.25 V.</td>

 10. Accuracy derived from Internal Main Oscillator with appropriate trim for V_{DD} range.

 11. 3.0 V < V_{DD} < 3.6 V.</td>

 12. See the individual user module data sheets for information on maximum frequencies for user modules.

 13. Refer to Cypress Jitter Specifications application note, Understanding Datasheet Jitter Specifications for Cypress Timing Products – AN5054 for more information.



Table 20. AC Chip-Level Specifications (continued)

Symbol	Description	Min	Тур	Max	Units	Notes
Fout48M	48 MHz Output Frequency	46.8	48.0	49.2 ^[9, 11]	MHz	Trimmed. Utilizing factory trim values.
F _{MAX}	Maximum frequency of signal on row input or row output.	-	-	12.3	MHz	-
SR _{POWER_} UP	Power Supply Slew Rate	_	-	250	V/ms	V_{DD} slew rate during power up.
T _{POWERUP}	Time from End of POR to CPU Executing Code	_	16	100	ms	Power up from 0V. See the System Resets section of the <i>PSoC</i> <i>Technical Reference Manual.</i>
tjit_IMO ^[13]	24 MHz IMO cycle-to-cycle jitter (RMS)	-	200	700	ps	
	24 MHz IMO long term N cycle-to-cycle jitter (RMS)	-	300	900		N = 32
	24 MHz IMO period jitter (RMS)	-	100	400		-
tjit_PLL ^[13]	24 MHz IMO cycle-to-cycle jitter (RMS)	_	200	800	ps	-
	24 MHz IMO long term N cycle-to-cycle jitter (RMS)	-	300	1200]	N = 32
	24 MHz IMO period jitter (RMS)	_	100	700		_

Figure 7. PLL Lock Timing Diagram

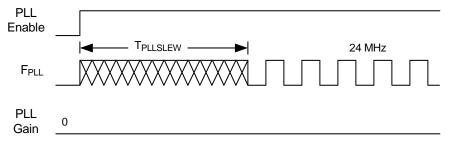
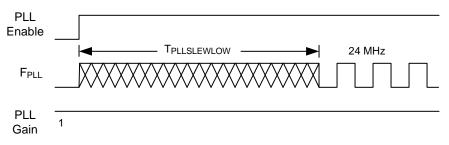
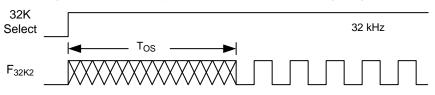


Figure 8. PLL Lock for Low Gain Setting Timing Diagram







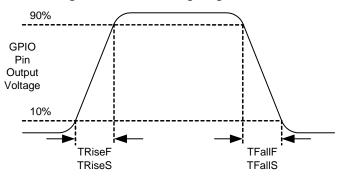


AC GPIO Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 21. AC GPIO Specifications

Symbol	Description	Min	Тур	Max	Units	Notes		
F _{GPIO}	GPIO operating frequency	0	-	12.3	MHz	Normal Strong Mode		
TRiseF	Rise time, normal strong mode, Cload = 50 pF	3	-	18	ns	V_{DD} = 4.75 to 5.25 V, 10% - 90%		
TFallF	Fall time, normal strong mode, Cload = 50 pF	2	-	18	ns	V_{DD} = 4.75 to 5.25 V, 10% - 90%		
TRiseS	Rise time, slow strong mode, Cload = 50 pF	10	27	-	ns	V _{DD} = 3 to 5.25 V, 10% - 90%		
TFallS	Fall time, slow strong mode, Cload = 50 pF	10	22	-	ns	V _{DD} = 3 to 5.25 V, 10% - 90%		







AC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and –40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Settling times, slew rates, and gain bandwidth are based on the Analog Continuous Time PSoC block.

Power = High and Opamp Bias = High is not supported at 3.3V.

Table 22. 5-V AC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{ROA}	Rising Settling Time to 0.1% for a 1 V Step (10 pF load, Unity Gain)					_
Ron	Power = Low, Opamp Bias = Low	_	-	3.9	μS	
	Power = Medium, Opamp Bias = High	—	-	0.72	μS	
	Power = High, Opamp Bias = High	—	-	0.62	μs	
T _{SOA}	Falling Settling Time to 0.1% for a 1 V Step (10 pF load, Unity Gain)					_
00/1	Power = Low, Opamp Bias = Low	_	-	5.9	μS	
	Power = Medium, Opamp Bias = High	_	-	0.92	μS	
	Power = High, Opamp Bias = High	-	-	0.72	μS	
SR _{ROA}	Rising Slew Rate (20% to 80%) of a 1 V Step (10 pF load, Unity Gain)					_
ite/t	Power = Low, Opamp Bias = Low	0.15	-	-	V/µs	
	Power = Medium, Opamp Bias = High	1.7	-	-	V/µs	
	Power = High, Opamp Bias = High	6.5	-	-	V/µs	
SR _{FOA}	Falling Slew Rate (20% to 80%) of a 1 V Step (10 pF load, Unity Gain)					_
1 0/1	Power = Low, Opamp Bias = Low	0.01	-	-	V/µs	
	Power = Medium, Opamp Bias = High	0.5	-	-	V/µs	
	Power = High, Opamp Bias = High	4.0	-	-	V/µs	
BW _{OA}	Gain Bandwidth Product					_
U.V.	Power = Low, Opamp Bias = Low	0.75	-	-	MHz	
	Power = Medium, Opamp Bias = High	3.1	-	-	MHz	
	Power = High, Opamp Bias = High	5.4	-	-	MHz	
E _{NOA}	Noise at 1 kHz (Power = Medium, Opamp Bias = High)	-	100	-	nV/rt-Hz	_

Table 23. 3.3-V AC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{ROA}	Rising settling time to 0.1% of a 1 V Step (10 pF load, Unity Gain)					_
	Power = Low, Opamp Bias = Low	_	-	3.92	μS	
	Power = Medium, Opamp Bias = High	-	-	0.72	μS	
T _{SOA}	Falling settling time to 0.1% of a 1 V Step (10 pF load, Unity Gain)					_
	Power = Low, Opamp Bias = Low	_	-	5.41	μS	
	Power = Medium, Opamp Bias = High	-	-	0.72	μS	
SR _{ROA}	Rising Slew Rate (20% to 80%) of a 1 V Step (10 pF load, Unity Gain)					_
	Power = Low, Opamp Bias = Low	0.31	-	-	V/µs	
	Power = Medium, Opamp Bias = High	2.7	-	-	V/µs	
SR _{FOA}	Falling slew rate (20% to 80%) of a 1 V Step (10 pF load, Unity Gain)					_
	Power = Low, Opamp Bias = Low	0.24	-	-	V/µs	
	Power = Medium, Opamp Bias = High	1.8	-	-	V/µs	
BW _{OA}	Gain bandwidth product					_
0.11	Power = Low, Opamp Bias = Low	0.67	-	-	MHz	
	Power = Medium, Opamp Bias = High	2.8	-	—	MHz	
E _{NOA}	Noise at 1 kHz (Power = Medium, Opamp Bias = High)	-	100	-	nV/rt-Hz	-





When bypassed by a capacitor on P2[4], the noise of the analog ground signal distributed to each block is reduced by a factor of up to 5 (14 dB). This is at frequencies above the corner frequency defined by the on-chip 8.1k resistance and the external capacitor.

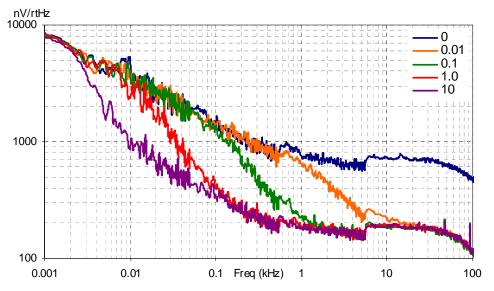


Figure 11. Typical AGND Noise with P2[4] Bypass

At low frequencies, the opamp noise is proportional to 1/f, power independent, and determined by device geometry. At high frequencies, increased power level reduces the noise spectrum level.

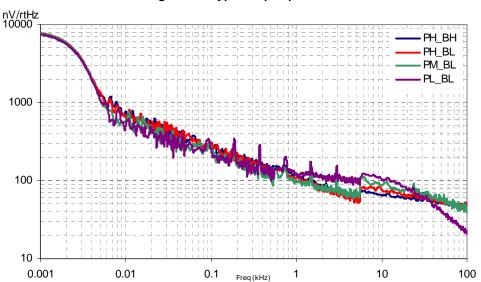


Figure 12. Typical Opamp Noise



AC Low Power Comparator Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 24. AC Low Power Comparator Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{RLPC}	LPC response time	1	1	50	μS	\geq 50 mV overdrive comparator reference set within V _{REFLPC} .

AC Digital Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 25. AC Digital Block Specifications

Function	Description	Min	Тур	Max	Unit	Notes
All functions	Block input clock frequency					
	$V_{DD} \ge 4.75 \text{ V}$	-	-	49.2	MHz	
	V _{DD} < 4.75 V	-	-	24.6	MHz	
Timer	Input clock frequency					
	No capture, $V_{DD} \ge 4.75 \text{ V}$	-	-	49.2	MHz	
	No capture, V _{DD} < 4.75 V	-	-	24.6	MHz	
	With capture	-	-	24.6	MHz	
	Capture pulse width	50 ^[14]	-	-	ns	
Counter	Input clock frequency					
	No enable input, $V_{DD} \ge 4.75 \text{ V}$	-	-	49.2	MHz	
	No enable input, V_{DD} < 4.75 V	-	-	24.6	MHz	
	With enable input	-	-	24.6	MHz	
	Enable input pulse width	50 ^[14]	-	-	ns	
Dead Band	Kill pulse width					
	Asynchronous restart mode	20	-	-	ns	
	Synchronous restart mode	50 ^[14]	-	-	ns	
	Disable mode	50 ^[14]	-	-	ns	
	Input clock frequency					
	$V_{DD} \ge 4.75 \text{ V}$	-	-	49.2	MHz	
	V _{DD} < 4.75 V	-	-	24.6	MHz	
CRCPRS	Input clock frequency					
(PRS Mode)	$V_{DD} \ge 4.75 \text{ V}$	-	-	49.2	MHz	
	V _{DD} < 4.75 V	-	-	24.6	MHz	
CRCPRS (CRC Mode)	Input clock frequency	-	-	24.6	MHz	
SPIM	Input clock frequency	_	-	8.2	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2
SPIS	Input clock (SCLK) frequency	-	-	4.1	MHz	The input clock is the SPI SCLK in SPIS mode
	Width of SS_negated between transmissions	50 ^[14]	_	_	ns	

Note 14.50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).



Table 25. AC Digital Block Specifications (continued)

Function	Description	Min	Тур	Max	Unit	Notes
Transmitter	Input clock frequency	The baud rate is equal to the input clock frequency				
	$V_{DD} \ge 4.75$ V, 2 stop bits	-	-	49.2	MHz	divided by 8
	$V_{DD} \ge 4.75$ V, 1 stop bit	-	-	24.6	MHz	
	V _{DD} < 4.75 V	-	-	24.6	MHz	
Receiver	Input clock frequency		•			The baud rate is equal to the input clock frequency
	$V_{DD} \ge 4.75$ V, 2 stop bits	-	-	49.2	MHz	divided by 8
	$V_{DD} \ge 4.75$ V, 1 stop bit	-	-	24.6	MHz	
	V _{DD} < 4.75 V	-	-	24.6	MHz	

AC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 26. 5V AC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{ROB}	Rising Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	-		4 4	μs μs	
T _{SOB}	Falling Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	-		3.4 3.4	μs μs	
SR _{ROB}	Rising Slew Rate (20% to 80%), 1 V Step, 100pF Load Power = Low Power = High	0.5 0.5			V/μs V/μs	
SR _{FOB}	Falling Slew Rate (80% to 20%), 1 V Step, 100pF Load Power = Low Power = High	0.55 0.55			V/μs V/μs	
BW _{OB}	Small Signal Bandwidth, 20mV _{pp} , 3dB BW, 100pF Load Power = Low Power = High	0.8 0.8			MHz MHz	
BW _{OB}	Large Signal Bandwidth, 1V _{pp} , 3dB BW, 100pF Load Power = Low Power = High	300 300			kHz kHz	



Table 27. 3.3V AC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{ROB}	Rising Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High			4.7 4.7	μs μs	
Τ _{SOB}	Falling Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High			4 4	μs μs	
SR _{ROB}	Rising Slew Rate (20% to 80%), 1 V Step, 100pF Load Power = Low Power = High	.36 .36	_		V/μs V/μs	
SR _{FOB}	Falling Slew Rate (80% to 20%), 1 V Step, 100pF Load Power = Low Power = High	.4 .4			V/μs V/μs	
BW _{OB}	Small Signal Bandwidth, 20mV _{pp} , 3dB BW, 100pF Load Power = Low Power = High	0.7 0.7			MHz MHz	
BW _{OB}	Large Signal Bandwidth, 1V _{pp} , 3dB BW, 100pF Load Power = Low Power = High	200 200	-		kHz kHz	

AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 28. 5V AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
FOSCEXT	Frequency	0.093	-	24.6	MHz	
-	High Period	20.6	-	5300	ns	
-	Low Period	20.6	-	-	ns	
-	Power Up IMO to Switch	150	-	-	μS	

Symbol	Description	Min	Тур	Max	Units	Notes
F _{OSCEXT}	Frequency with CPU Clock Divide by 1	0.093	-	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F _{OSCEXT}	Frequency with CPU Clock Divide by 2 or Greater	0.186	-	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider will ensure that the fifty percent duty cycle requirement is met.
-	High Period with CPU Clock Divide by 1	41.7	-	5300	ns	-
-	Low Period with CPU Clock Divide by 1	41.7	_	-	ns	_
-	Power Up IMO to Switch	150	-	_	μS	_



AC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 30. AC Programming Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{RSCLK}	Rise Time of SCLK	1	-	20	ns	-
T _{FSCLK}	Fall Time of SCLK	1	-	20	ns	-
T _{SSCLK}	Data Set up Time to Falling Edge of SCLK	40	-	-	ns	-
T _{HSCLK}	Data Hold Time from Falling Edge of SCLK	40	-	-	ns	-
F _{SCLK}	Frequency of SCLK	0	-	8	MHz	-
T _{ERASEB}	flash Erase Time (Block)	-	10	-	ms	-
T _{WRITE}	flash Block Write Time	-	40	-	ms	-
T _{DSCLK}	Data Out Delay from Falling Edge of SCLK	-	-	45	ns	V _{DD} > 3.6
T _{DSCLK3}	Data Out Delay from Falling Edge of SCLK	-	-	50	ns	$3.0 \leq V_{DD} \leq 3.6$
T _{ERASEALL}	flash Erase Time (Bulk)	_	80	_	ms	Erase all blocks and protection fields at once.
T _{PROGRAM_HOT}	flash Block Erase + flash Block Write Time	_	-	100 ^[15]	ms	$0^{\circ}C \leq T_{J} \leq 100 \ ^{\circ}C$
T _{PROGRAM_COLD}	flash Block Erase + flash Block Write Time	_	_	200 ^[15]	ms	$-40^{\circ}C \leq T_{J} \leq 0 \ ^{\circ}C$

Note

^{15.} For the full industrial range, the user must employ a Temperature Sensor User Module (flashTemp) and feed the result to the temperature argument before writing. Refer to the flash APIs Application Note AN2015 at http://www.cypress.com under Application Notes for more information.



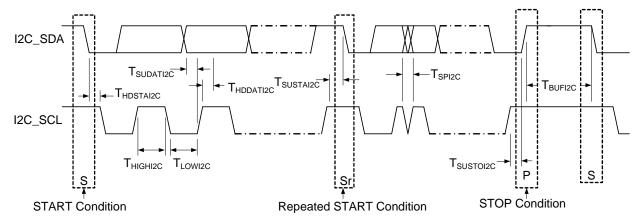
AC I²C Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C \leq T_A \leq 85 °C, or 3.0 V to 3.6 V and -40 °C \leq T_A \leq 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 31.	AC Characteristics	of the I ² C SDA a	nd SCL Pins
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Symbol	Description		d-Mode	Fast-	Mode	Units	Notes
Symbol	Description	Min	Max	Min	Max	Units	NOLES
F _{SCLI2C}	SCL Clock Frequency	0	100	0	400	kHz	-
T _{HDSTAI2C}	Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	4.0	-	0.6	-	μS	_
T _{LOWI2C}	LOW Period of the SCL Clock	4.7	-	1.3	-	μS	-
T _{HIGHI2C}	HIGH Period of the SCL Clock	4.0	-	0.6	-	μS	-
T _{SUSTAI2C}	Set-up Time for a Repeated START Condition	4.7		0.6	_	μS	_
T _{HDDATI2C}	Data Hold Time	0	-	0	-	μS	_
T _{SUDATI2C}	Data Set-up Time	250	-	100 ^[16]	-	ns	-
T _{SUSTOI2C}	Set-up Time for STOP Condition	4.0	-	0.6	-	μS	-
T _{BUFI2C}	Bus Free Time Between a STOP and START Condition	4.7	-	1.3	-	μS	_
T _{SPI2C}	Pulse Width of spikes are suppressed by the input filter.	_	_	0	50	ns	_





Note

16. A Fast-Mode I2C-bus device can be used in a Standard-Mode I2C-bus system, but the requirement t_{SU:DAT} ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t_{rmax} + t_{SU;DAT} = 1000 + 250 = 1250 ns (according to the Standard-Mode I2C-bus specification) before the SCL line is released.



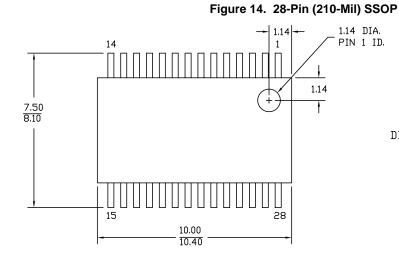


Packaging Information

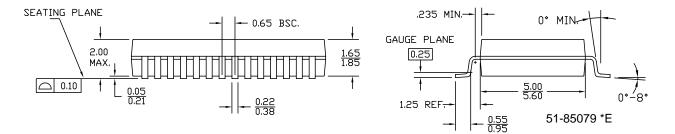
This section illustrates the packaging specifications for the CY8CLED16 EZ-Color device, along with the thermal impedances for each package and the typical package capacitance on crystal pins.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at http://www.cypress.com.

Packaging Dimensions



DIMENSIONS IN MILLIMETERS MIN. MAX.





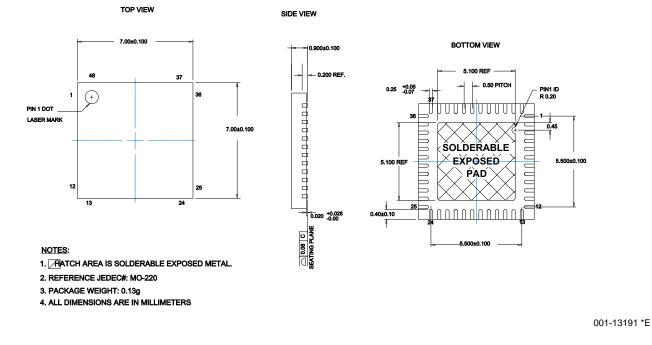


Figure 15. 48-Pin (7 × 7 × 1.0 mm) QFN (Sawn)

Important Note

For information on the preferred dimensions for mounting QFN packages, see the following Application Note "Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages" available at http://www.amkor.com.

Pinned vias for thermal conduction are not required for the low-power device.

Thermal Impedances

Table 32. Thermal Impedances per Package

Package	Typical θ _{JA} ^[17]
28 SSOP	94 °C/W
48 QFN ^[18]	28 °C/W

Capacitance on Crystal Pins

Table 33. Typical Package Capacitance on Crystal Pins

Package	Package Capacitance
28 SSOP	2.8 pF
48 QFN	1.8 pF

Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

Table 34. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Time at Maximum Peak Temperature
28 SSOP	260 °C	30 s
48 QFN	260 °C	30 s

Notes

17. $T_J = T_A + POWER \times \theta_{JA}$

18. To achieve the thermal impedance specified for the QFN package, refer to "Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages" available at http://www.amkor.com.



Development Tool Selection

Software

PSoC Designer™

At the core of the PSoC development software suite is PSoC Designer, used to generate PSoC firmware applications. PSoC Designer is available free of charge at http://www.cypress.com and includes a free C compiler.

PSoC Programmer

PSoC Programmer is flexible and used on the bench in development. It is also suitable for factory programming. PSoC Programmer works either as a standalone programming application or operates directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE Cube In-Circuit Emulator and PSoC MiniProg. It is available free of charge at http://www.cypress.com.

Evaluation Tools

All evaluation tools are sold at the Cypress Online Store.

CY3210-MiniProg1

The CY3210-MiniProg1 kit enables the user to program PSoC devices via the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC via a provided USB 2.0 cable. The kit includes:

- MiniProg programming unit
- MiniEval Socket Programming and Evaluation board
- 28-Pin CY8C29466-24PXI PDIP PSoC device sample
- 28-Pin CY8C27443-24PXI PDIP PSoC device sample
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3210-PSoCEval1

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- Evaluation board with LCD module
- MiniProg programming unit
- 28-Pin CY8C29466-24PXI PDIP PSoC Device Sample (2)
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

Device Programmers

All device programmers are sold at the Cypress Online Store.

CY3216 Modular Programmer

The CY3216 Modular Programmer kit features a modular programmer and the MiniProg1 programming unit. The modular programmer includes three programming module cards and supports multiple Cypress products. The kit includes:

- Modular Programmer Base
- Three Programming Module cards
- MiniProg programming unit
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3207ISSP In-System Serial Programmer (ISSP)

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production programming environment. Note that CY3207ISSP needs special software and is not compatible with PSoC Programmer. The kit includes:

- CY3207 programmer unit
- PSoC ISSP software CD
- 110 ~ 240V power supply, euro-plug adapter
- USB 2.0 cable



Accessories (Emulation and Programming)

Table 35. Emulation and Programming Accessories

Part No.	Pin Package	Flex-Pod Kit ^[19]	Foot Kit ^[20]	Adapter ^[21]
CY8CLED16-48LFXI	48-pin QFN	CY3250-LED16QFN		Adapters can be found at http://www.emulation.com.

Ordering Information

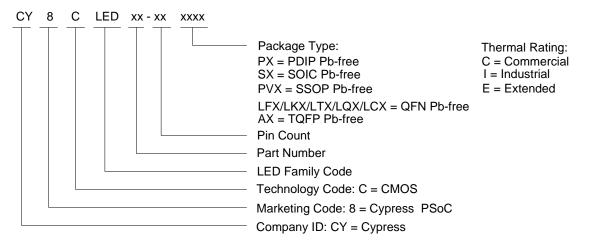
Key Device Features

The following table lists the CY8CLED16 EZ-Color devices' key package features and ordering codes.

Table 36. Device Key Features and Ordering Information

Package Ordering Code		Flash (Bytes)	RAM (Bytes)	Switch Mode Pump	Temperature Range	Digital PSoC Blocks	Analog PSoC Blocks	Digital I/O Pins	Analog Inputs	Analog Outputs	XRES Pin
48-Pin QFN (Sawn)	CY8CLED16-48LTXI	32 K	2 K	Yes	–40 °C to +85 °C	16	12	44	12	4	Yes
48-Pin QFN (Tape and Reel) (Sawn)	CY8CLED16-48LTXIT	32 K	2 K	Yes	–40 °C to +85 °C	16	12	44	12	4	Yes

Ordering Code Definitions



Notes

19. Flex-Pod kit includes a practice flex-pod and a practice PCB, in addition to two flex-pods.

20. Foot kit includes surface mount feet that can be soldered to the target PCB.

^{21.} Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at http://www.emulation.com.



Acronyms

Acronyms Used

Table 37 lists the acronyms that are used in this document.

Table 37. Acronyms Used in this Datasheet

Acronym	Description	Acronym	Description
AC	alternating current	MAC	multiply-accumulate
ADC	analog-to-digital converter	MIPS	million instructions per second
API	application programming interface	PCB	printed circuit board
CMOS	complementary metal oxide semiconductor	PDIP	plastic dual-in-line package
CPU	central processing unit	PLL	phase-locked loop
CRC	cyclic redundancy check	POR	power-on reset
СТ	continuous time	PPOR	precision power on reset
DAC	digital-to-analog converter	PRS	pseudo-random sequence
DC	direct current	PSoC [®]	Programmable System-on-Chip
DTMF	dual-tone multi-frequency	PWM	pulse-width modulator
ECO	external crystal oscillator	QFN	quad flat no leads
EEPROM	EPROM electrically erasable programmable read-only memory		real time clock
GPIO	general purpose I/O	SAR	successive approximation
ICE	in-circuit emulator	SC	switched capacitor
IDE	integrated development environment	SMP	switch mode pump
ILO	internal low speed oscillator	SPI	serial peripheral interface
IMO	internal main oscillator	SRAM	static random access memory
I/O	input/output	SROM	supervisory read only memory
IrDA	infrared data association	SSOP	shrink small-outline package
ISSP	in-system serial programming	UART	universal asynchronous reciever / transmitter
LCD	liquid crystal display	USB	universal serial bus
LED	light-emitting diode	WDT	watchdog timer
LPC	low power comparator	XRES	external reset
LVD	low-voltage detect		

Reference Documents

Design Aids – Reading and Writing $PSoC^{\textcircled{B}}$ Flash – AN2015 (001-40459)

Understanding Datasheet Jitter Specifications for Cypress Timing Products – AN5054 (001-14503)

Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages – available at http://www.amkor.com.



Document Conventions

Units of Measure

Table 38 lists the units of measures.

Table 38. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
dB	decibels	ms	milliseconds
°C	degree Celsius	mH	millihenry
fF	femtofarad	ns	nanoseconds
kHz	kilohertz	μV	microvolts
kΩ	kilohm	V	volts
MHz	megahertz	mV	millivolts
μA	microamperes	μW	microwatts
μs	microseconds	%	percent
mA	milliamperes	W	watt
nA	nanoamperes	mm	millimeters
pF	picofarad	ps	picosecond
pА	pikoamperes	ppm	parts per million
rt-Hz	root hertz	nV	nanovolts

Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, 01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or 0x are decimals.

Glossary

active high	 A logic signal having its asserted state as the logic 1 state. A logic signal having the logic 1 state as the higher voltage of the two states.
analog blocks	The basic programmable opamp circuits. These are switched capacitor (SC) and continuous time (CT) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
Application programming interface (API)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of VT with the negative temperature coefficient of VBE, to produce a zero temperature coefficient (ideally) reference.
bandwidth	 The frequency range of a message or information processing system measured in hertz. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.



bias	1. A systematic deviation of a value from a reference value.
	2. The amount by which the average of a set of values departs from a reference value.
	The electrical, mechanical, magnetic, or other force (field) applied to a device to establish a reference level to operate the device.
block	1. A functional unit that performs a single function, such as an oscillator.
	 A functional unit that may be configured to perform one of several functions, such as a digital PSoC block or an analog PSoC block.
buffer	 A storage area for data that is used to compensate for a speed difference, when transferring data from one device to another. Usually refers to an area reserved for IO operations, into which data is read, or from which data is written.
	A portion of memory set aside to store data, often before it is sent to an external device or as it is received from an external device.
	3. An amplifier used to lower the output impedance of a system.
bus	 A named connection of nets. Bundling nets together in a bus makes it easier to route nets with similar routing patterns.
	A set of signals performing a common function and carrying similar data. Typically represented using vector notation; for example, address[7:0].
	3. One or more conductors that serve as a common connection for a group of related devices.
clock	The device that generates a periodic signal with a fixed frequency and duty cycle. A clock is sometimes used to synchronize different logic blocks.
comparator	An electronic circuit that produces an output voltage or current whenever two input levels simultaneously satisfy predetermined amplitude requirements.
compiler	A program that translates a high level language, such as C, into machine language.
configuration space	In PSoC devices, the register space accessed when the XIO bit, in the CPU_F register, is set to '1'.
crystal oscillator	An oscillator in which the frequency is controlled by a piezoelectric crystal. Typically a piezoelectric crystal is less sensitive to ambient temperature than other circuit components.
cyclic redundancy check (CRC)	A calculation used to detect errors in data communications, typically performed using a linear feedback shift register. Similar calculations may be used for a variety of other purposes such as data compression.
data bus	A bi-directional set of signals used by a computer to convey information from a memory location to the central processing unit and vice versa. More generally, a set of signals used to convey data between digital functions.
debugger	A hardware and software system that allows you to analyze the operation of the system under development. A debugger usually allows the developer to step through the firmware one step at a time, set break points, and analyze memory.
dead band	A period of time when neither of two or more signals are in their active state or in transition.
digital blocks	The 8-bit logic blocks that can act as a counter, timer, serial receiver, serial transmitter, CRC generator, pseudo-random number generator, or SPI.



digital-to-analog (DAC)	A device that changes a digital signal to an analog signal of corresponding magnitude. The analog- to-digital (ADC) converter performs the reverse operation.
duty cycle	The relationship of a clock period high time to its low time, expressed as a percent.
emulator	Duplicates (provides an emulation of) the functions of one system with a different system, so that the second system appears to behave like the first system.
External Reset (XRES)	An active high signal that is driven into the PSoC device. It causes all operation of the CPU and blocks to stop and return to a pre-defined state.
flash	An electrically programmable and erasable, non-volatile technology that provides you the programmability and data storage of EPROMs, plus in-system erasability. Non-volatile means that the data is retained when power is OFF.
flash block	The smallest amount of flash ROM space that may be programmed at one time and the smallest amount of flash space that may be protected. A flash block holds 64 bytes.
frequency	The number of cycles or events per unit of time, for a periodic function.
gain	The ratio of output current, voltage, or power to input current, voltage, or power, respectively. Gain is usually expressed in dB.
I ² C	A two-wire serial computer bus by Philips Semiconductors (now NXP Semiconductors). I^2C is an Inter-Integrated Circuit. It is used to connect low-speed peripherals in an embedded system. The original system was created in the early 1980s as a battery control interface, but it was later used as a simple internal bus system for building control electronics. I2C uses only two bi-directional pins, clock and data, both running at +5 V and pulled high with resistors. The bus operates at 100 kbits/second in standard mode and 400 kbits/second in fast mode.
ICE	The in-circuit emulator that allows you to test the project in a hardware environment, while viewing the debugging device activity in a software environment (PSoC Designer).
input/output (I/O)	A device that introduces data into or extracts data from a system.
interrupt	A suspension of a process, such as the execution of a computer program, caused by an event external to that process, and performed in such a way that the process can be resumed.
interrupt service routine (ISR)	A block of code that normal code execution is diverted to when the M8C receives a hardware interrupt. Many interrupt sources may each exist with its own priority and individual ISR code block. Each ISR code block ends with the RETI instruction, returning the device to the point in the program where it left normal program execution.
jitter	1. A misplacement of the timing of a transition from its ideal position. A typical form of corruption that occurs on serial data streams.
	The abrupt and unwanted variations of one or more signal characteristics, such as the interval between successive pulses, the amplitude of successive cycles, or the frequency or phase of successive cycles.
low-voltage detect (LVD)	A circuit that senses V_{DD} and provides an interrupt to the system when V_{DD} falls lower than a selected threshold.
M8C	An 8-bit Harvard-architecture microprocessor. The microprocessor coordinates all activity inside

a PSoC by interfacing to the flash, SRAM, and register space.



master device	A device that controls the timing for data exchanges between two devices. Or when devices are cascaded in width, the master device is the one that controls the timing for data exchanges between the cascaded devices and an external interface. The controlled device is called the <i>slave device</i> .
microcontroller	An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for general-purpose computation as is a microprocessor.
mixed-signal	The reference to a circuit containing both analog and digital techniques and components.
modulator	A device that imposes a signal on a carrier.
noise	 A disturbance that affects a signal and that may distort the information carried by the signal. The random variations of one or more characteristics of any entity such as voltage, current, or data.
oscillator	A circuit that may be crystal controlled and is used to generate a clock frequency.
parity	A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the digits of the binary data either always even (even parity) or always odd (odd parity).
Phase-locked loop (PLL)	An electronic circuit that controls an oscillator so that it maintains a constant phase angle relative to a reference signal.
pinouts	The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between schematic and PCB design (both being computer generated files) and may also involve pin names.
port	A group of pins, usually eight.
Power on reset (POR)	A circuit that forces the PSoC device to reset when the voltage is lower than a pre-set level. This is a type of hardware reset.
PSoC [®]	Cypress Semiconductor's PSoC [®] is a registered trademark and Programmable System-on- Chip™ is a trademark of Cypress.
PSoC Designer™	The software for Cypress' Programmable System-on-Chip technology.
pulse width modulator (PWM)	An output in the form of duty cycle which varies as a function of the applied measurand
RAM	An acronym for random access memory. A data-storage device from which data can be read out and new data can be written in.
register	A storage device with a specific capacity, such as a bit or byte.
reset	A means of bringing a system back to a know state. See hardware reset and software reset.
ROM	An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot be written in.



serial	1. Pertaining to a process in which all events occur one after the other.
	2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or channel.
settling time	The time it takes for an output signal or value to stabilize after the input has changed from one value to another.
shift register	A memory storage device that sequentially shifts a word either left or right to output a stream of serial data.
slave device	A device that allows another device to control the timing for data exchanges between two devices. Or when devices are cascaded in width, the slave device is the one that allows another device to control the timing of data exchanges between the cascaded devices and an external interface. The controlling device is called the master device.
SRAM	An acronym for static random access memory. A memory device where you can store and retrieve data at a high rate of speed. The term static is used because, after a value is loaded into an SRAM cell, it remains unchanged until it is explicitly altered or until power is removed from the device.
SROM	An acronym for supervisory read only memory. The SROM holds code that is used to boot the device, calibrate circuitry, and perform flash operations. The functions of the SROM may be accessed in normal user code, operating from flash.
stop bit	A signal following a character or block that prepares the receiving device to receive the next character or block.
synchronous	 A signal whose data is not acknowledged or acted upon until the next active edge of a clock signal. A system whose operation is synchronized by a clock signal.
tri-state	A function whose output can adopt three states: 0, 1, and Z (high-impedance). The function does not drive any value in the Z state and, in many respects, may be considered to be disconnected from the rest of the circuit, allowing another output to drive the same net.
UART	A UART or universal asynchronous receiver-transmitter translates between parallel bits of data and serial bits.
user modules	Pre-build, pre-tested hardware/firmware peripheral functions that take care of managing and configuring the lower level Analog and Digital PSoC Blocks. User Modules also provide high level API (Application Programming Interface) for the peripheral function.
user space	The bank 0 space of the register map. The registers in this bank are more likely to be modified during normal program execution and not just during initialization. Registers in bank 1 are most likely to be modified only during the initialization phase of the program.
V _{DD}	A name for a power net meaning "voltage drain." The most positive power supply signal. Usually 5 V or 3.3 V.
V _{SS}	A name for a power net meaning "voltage source." The most negative power supply signal.
watchdog timer	A timer that must be serviced periodically. If it is not serviced, the CPU resets after a specified period of time.



Document History Page

Document	Number: 00		Submission	
Revision	ECN No	Origin of Change	Submission Date	Description of Change
**	1148504	SFVTMP3	See ECN	New document (revision **).
*A	2763950	DPT	09/29/2009	Added 48QFN package diagram (Sawn). Added Saw Marketing part number in ordering information.
*В	2794355	XBM	10/28/2009	Added "Contents" on page 3 Updated "Development Tools" on page 7. Corrected FCPU1 and FCPU2 parameters in "AC Chip-Level Specifica- tions" on page 31.
*C	2850593	FRE	01/14/2010	Updated DC GPIO, AC Chip-Level, and AC Programming Specifications as follows: Replaced TRAMP (time) with SRPOWER_UP (slew rate) specification. Added note to flash Endurance specification. Added IOH, IOL, DCILO, F32K_U, TPOWERUP, TERASEALL, TPROGRAM_HOT, and TPROGRAM_COLD specifications. Corrected the Pod Kit part numbers. Updated Development Tool Selection. Updated copyright and Sales, Solutions, and Legal Information URLs. Updated 28-Pin SSOP 48-Pin QFN (Punched), 48-Pin QFN (Sawn) package diagrams. Removed Preliminary for Final status.
*D	2896238	CGX	03/19/10	Updated ordering information table. Removed part numbers CY8CLED16-48LFXI and CY8CLED16-48LFXIT Updated copyright section. Updated package diagram for spec 51-85061
*E	2903043	NJF	04/01/2010	Updated Cypress website links Added T _{BAKETEMP} and T _{BAKETIME} parameters Removed reference to 2.4V Removed sections "Third Party Tools" and "Build a PSoC Emulator"
*F	3054665	CGX	10/11/2010	Removed pruned parts CY8CLED16-48PVXI and CY8CLED16-48PVXIT
*G	3114959	NJF	12/19/10	Added DC I ² C Specifications table. Added F _{32K U} max limit. Added Tjit_IMO specification, removed existing jitter specifications. Updated DC Analog reference, DC operational amplifier specifications and DC analog output buffer specifications tables. Updated Units of Measure, Acronyms, Glossary, and References sections. Updated solder reflow specifications. No specific changes were made to AC Digital Block Specifications table and I ² C Timing Diagram. They were updated for clearer understanding. Updated Figure 12 since the labelling for y-axis was incorrect. Removed footnote reference for "Solder Reflow Peak Temperature" table.
*H	3284932	SHOB	06/24/11	Updated Getting Started, Development Tools, and Designing with PSoC Designer. Removed drawings and references to 48-Pin QFN (Punched) and 48-Pin SSOP. Removed obsolete kits. Removed reference to obsolete spec AN2012.
*	3403622	10/12/11	МККU	Removed the following pruned parts from the Ordering Information and Accessories (Emulation and Programming) sections. CY8CLED16-28PVXI CY8CLED16-28PVXIT



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